

VERTEX DETECTOR AT FCC-EE

LAYOUT UPDATES AND POSSIBLE IMPROVEMENTS

Fabrizio Palla¹

Manuela Boscolo ², Filippo Bosi ¹, Francesco Franesini ², Armin Ilg ³, Stefano Lauciani ²

¹*INFN Sezione di Pisa, Italy*

²*INFN Laboratori Nazionali di Frascati (RM), Italy*

³*Zurich University*

*7th FCC Physics workshop
Annecy (France)
29 January – 2 February 2024*

Outline

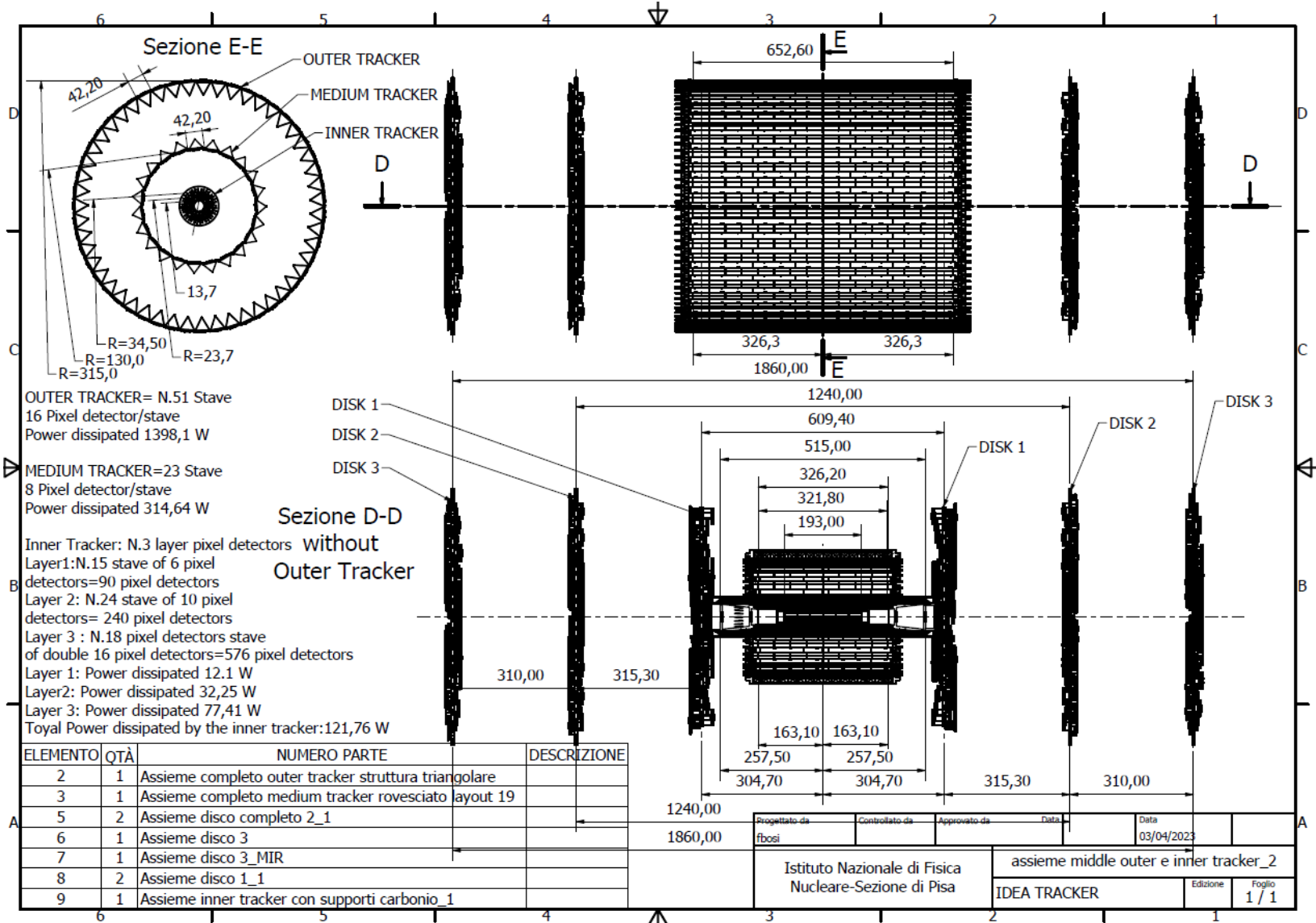
- ❑ **Mid-Term Feasibility Vertex layout**
 - ❑ Updated Inner and Outer vertex mechanical description
 - ❑ Study of the services routings
- ❑ **Toward material budget reduction**
 - ❑ Some critical issues using curved sensors
- ❑ **Conclusions**

Requirements

Interaction region detectors must be integrated with the beam pipe

- The vertex detector innermost radius should profit of the reduced beam pipe diameter (2 cm) and should cover $|\cos\theta| < 0.99$
- **Must not interfere with the Luminosity Calorimeter (clearance of ~120 mrad)**
- **The mounting of the vertex tracker must be done inside the support tube**
- Minimize the radiation lengths

Mid-term review vertex detector overall layout



Outer vertex tracker:

Modules of $50 \times 150 \mu\text{m}^2$ pixel size

- Intermediate barrel at 13 cm radius (improved reconstruction for $p_T > 40$ MeV tracks)
- Outer barrel at 31.5 cm radius
- 3 disks per side

Inner Vertex detector:

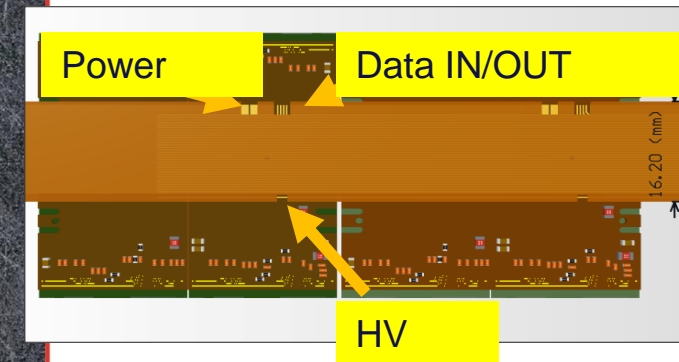
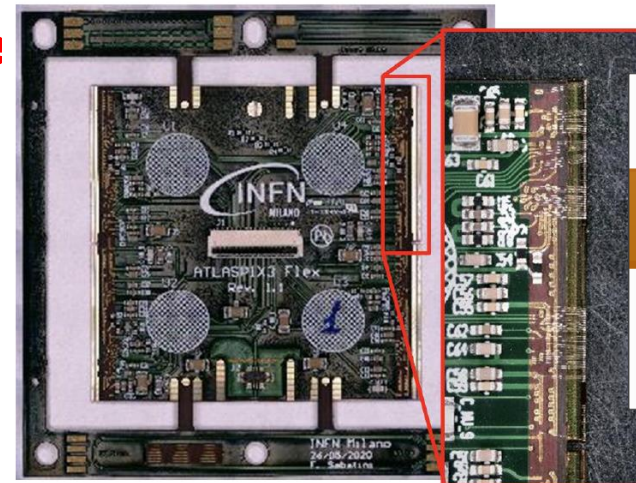
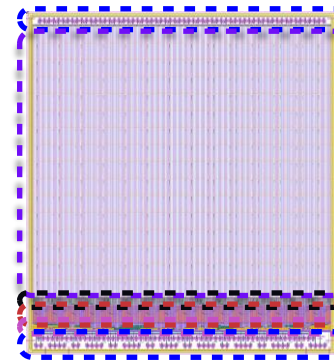
Modules of $25 \times 25 \mu\text{m}^2$ pixel size

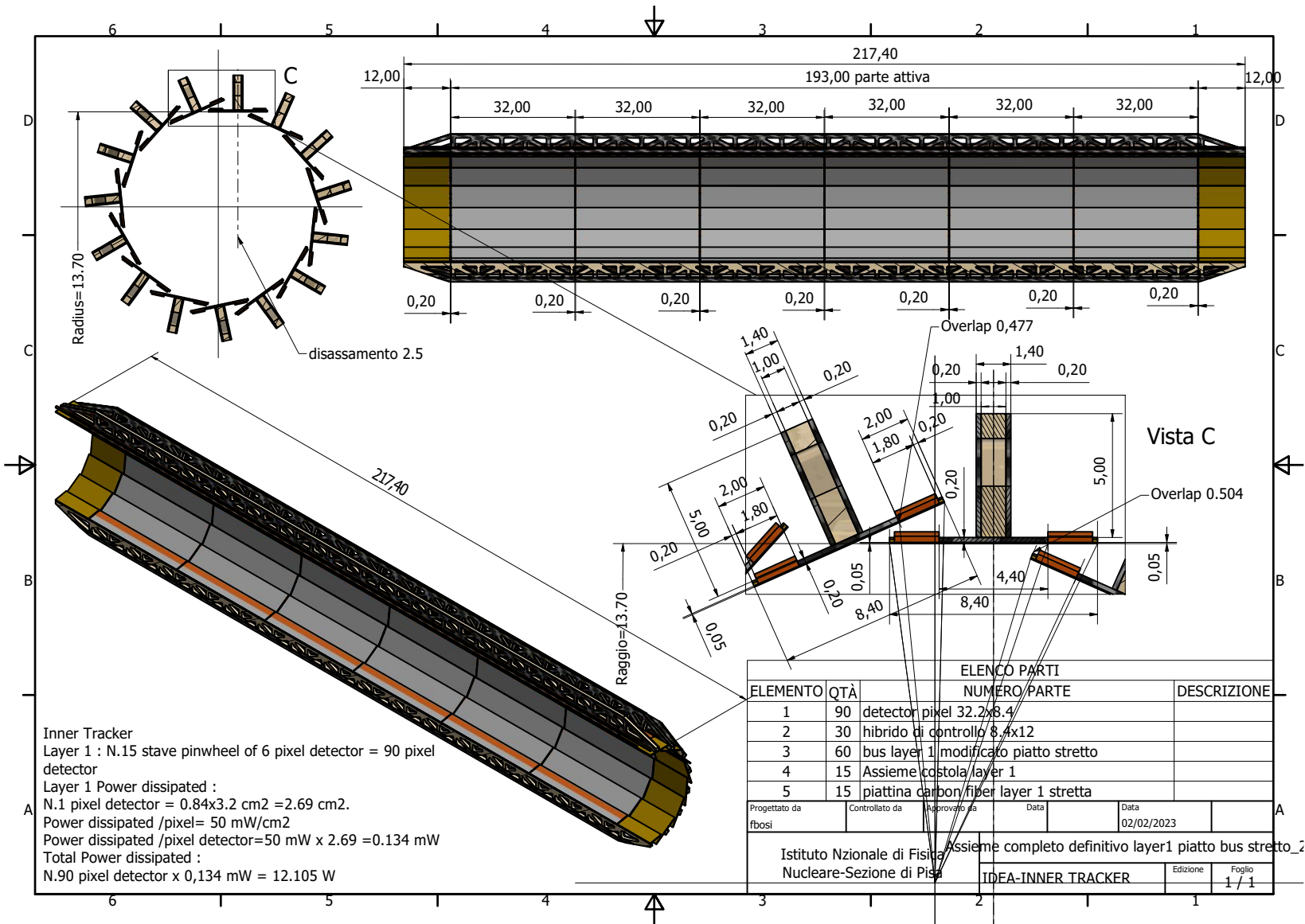
3 barrel layers at
- 13.7, 22.7 and 34.8 mm radius

Sensors technology and dimensions

Depleted Monolithic Active Pixel Detectors

- **Inner Vertex (ARCADIA based):**
 - Lfoundry 110 nm process
 - *50 μm thick*
 - Dimensions: $8.4 \times 32 \text{ mm}^2$
 - Power density 50 mW/cm^2
 - **100 MHz/cm²**
- **Outer Vertex and disks (ATLASPIX3 base)**
 - TSI 180 nm process
 - *50 μm thick*
 - Module dimensions: $42.2 \times 40.6 \text{ mm}^2$
 - Power density 100 mW/cm^2
 - **Up to 1.28 Gb/s downlink**





Inner Tracker
 Layer 1 : N.15 stave pinwheel of 6 pixel detector = 90 pixel detector
 Layer 1 Power dissipated :
 N.1 pixel detector = 0.84x3.2 cm2 = 2.69 cm2.
 Power dissipated /pixel= 50 mW/cm2
 Power dissipated /pixel detector=50 mW x 2.69 =0.134 mW
 Total Power dissipated :
 N.90 pixel detector x 0,134 mW = 12.105 W

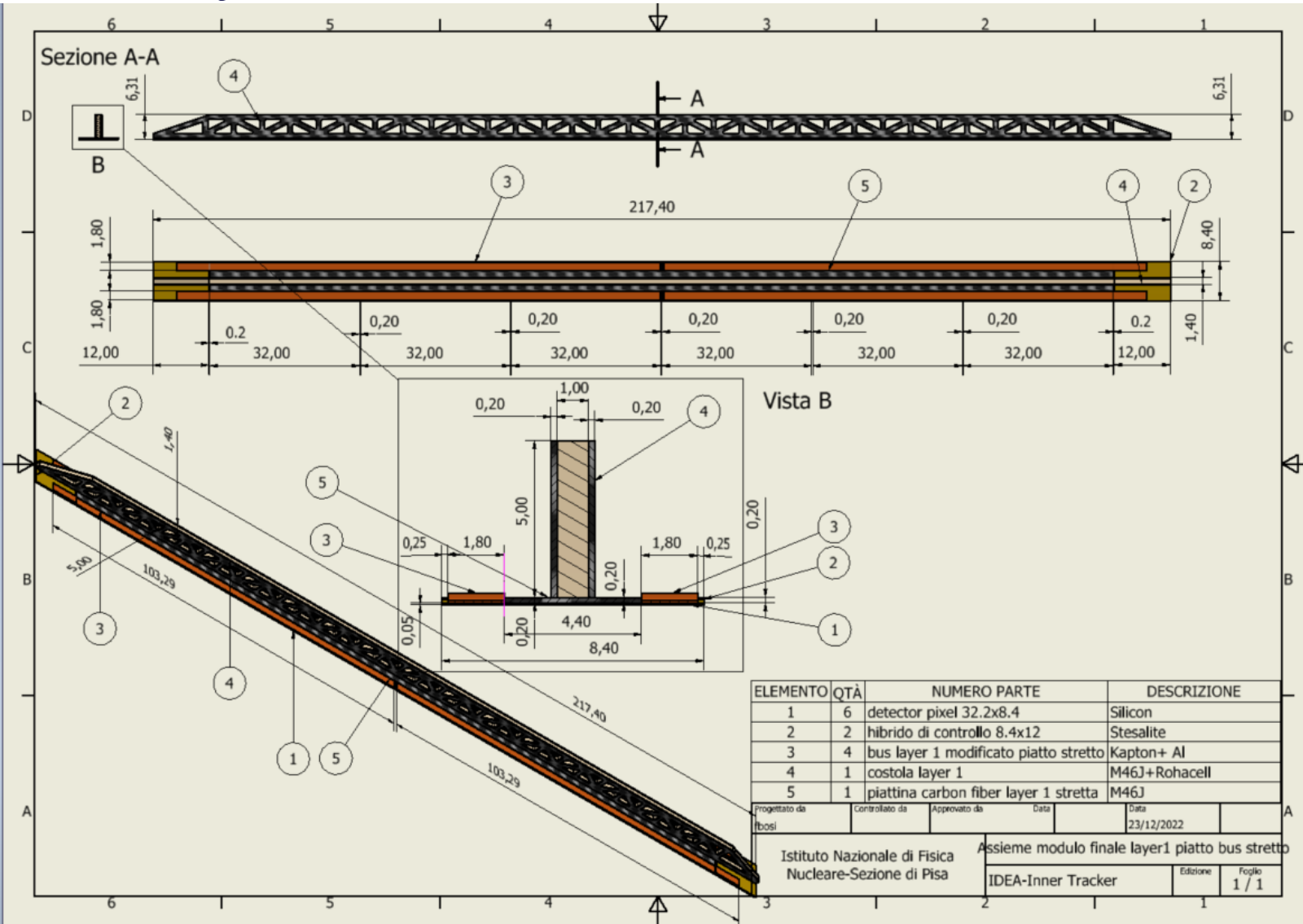
ELENCO PARTI			
ELEMENTO	QTÀ	NUMERO/PARTE	DESCRIZIONE
1	90	detector pixel 32.2x8.4	
2	30	ibrido di controllo 8.4x12	
3	60	bus layer 1, modificato piatto stretto	
4	15	Assieme costola layer 1	
5	15	piattina carbon fiber layer 1 stretta	

Progettato da	Controllato da	Approvato da	Data
fbosi			02/02/2023

Istituto Nazionale di Fisica Nucleare-Sezione di Pisa		Assieme completo definitivo layer1 piatto bus stretto_2	
IDEA-INNER TRACKER		Edizione	Foglio
			1 / 1

Layer 1
 15 overlapping staves of 6 modules each
 Overlap to allow alignment ~500 μm
 Pinwheel geometry: all modules at the same (smallest) radius
Power budget ~12 W
Total weight ~22 grams
 Total thickness 0.25% X₀
 Silicon: 0.053% X₀
 Power and readout bus: 0.056% X₀

Layer 1 stave detail



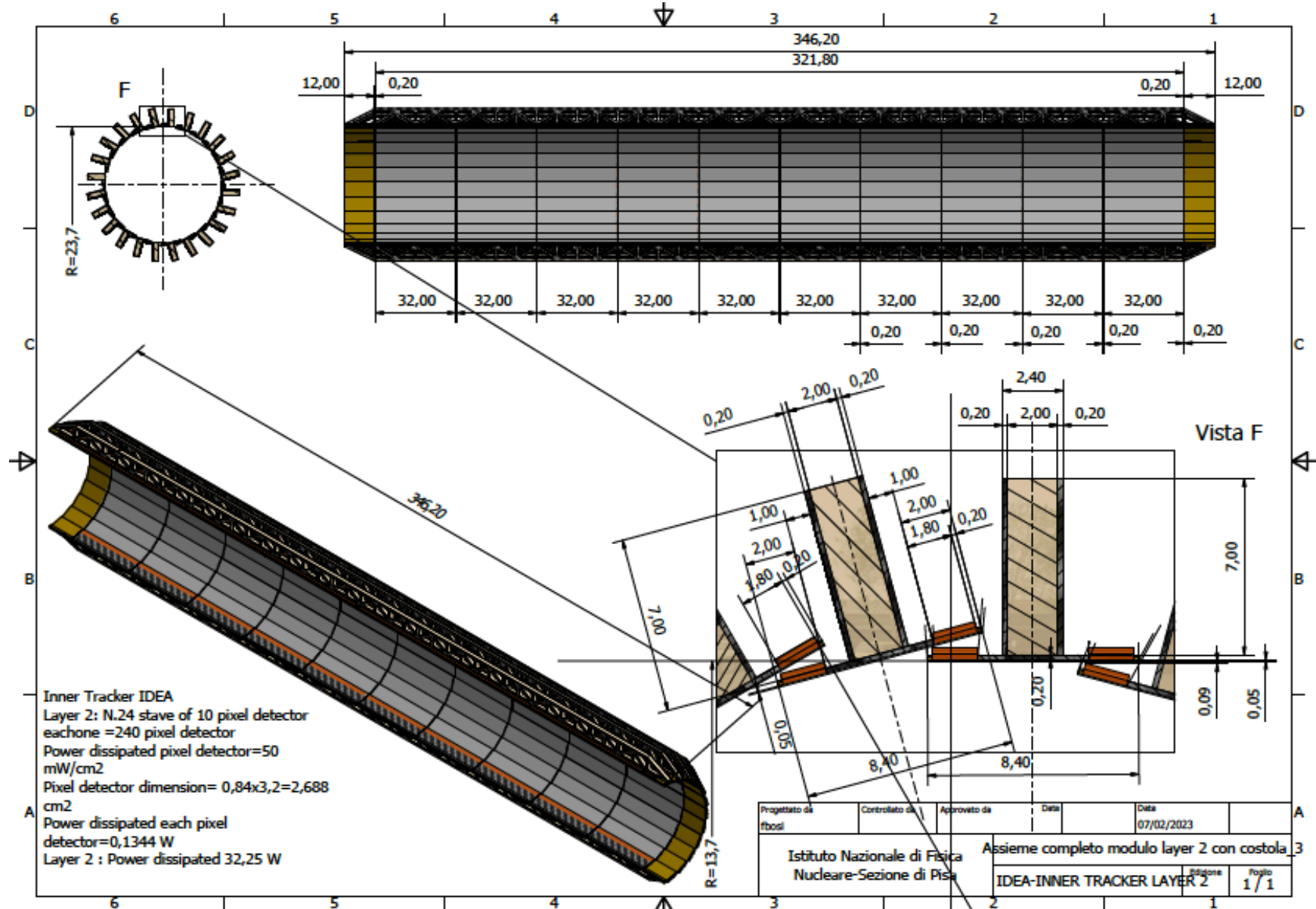
Reticular lightweight support to provide stiffness

- Thin carbon fiber walls interleaved with Rohacell
- 2 buses (data and power) 1.8 mm wide and 250 μm thick (50 μm Al, 200 μm kapton) per side
 - Inspired to low mass hybrid R&D

Sensors facing interaction point w/o any other material in front

Readout chips either sides

Air cooled



Inner Tracker IDEA
 Layer 2: N.24 stave of 10 pixel detector
 eachone =240 pixel detector
 Power dissipated pixel detector=50
 mW/cm²
 Pixel detector dimension= 0,84x3,2=2,688
 cm²
 Power dissipated each pixel
 detector=0,1344 W
 Layer 2 : Power dissipated 32,25 W

Progettato da fposi	Controllato da	Approvato da	Data	Data 07/02/2023
Istituto Nazionale di Fisica Nucleare-Sezione di Pisa			Assemble completo modulo layer 2 con costola	
			Disegno IDEA-INNER TRACKER LAYER 2	Foglio 1 / 1

Layer 2
 24 overlapping staves of
 10 modules each

Pinwheel geometry
 Counter-rotated wrt layer
 1 to mitigate charge-
 asymmetry effects in
 track reconstruction

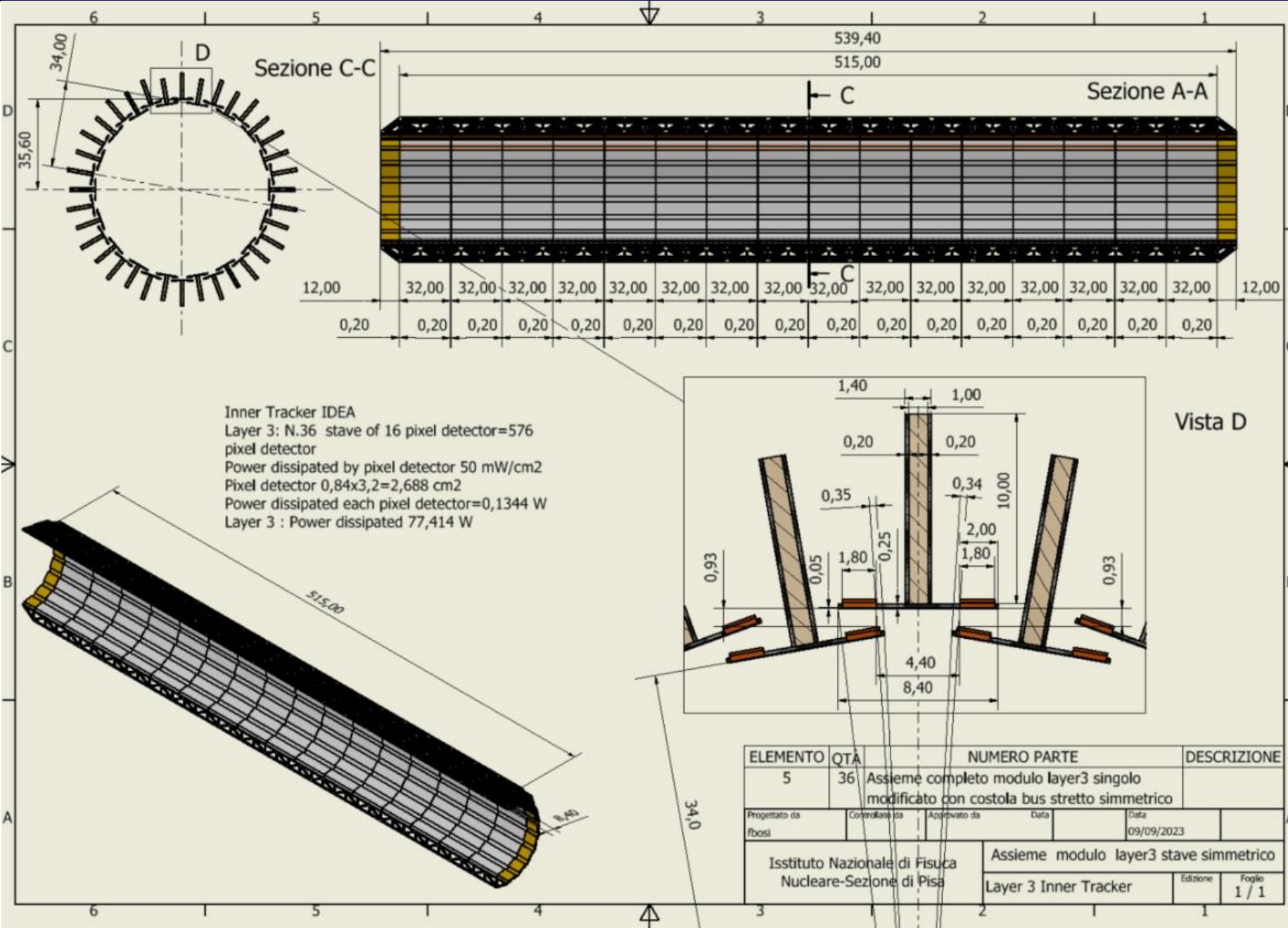
Power budget
 ~32 W

Total weight ~63 grams

Total thickness 0.25% X₀



NEW



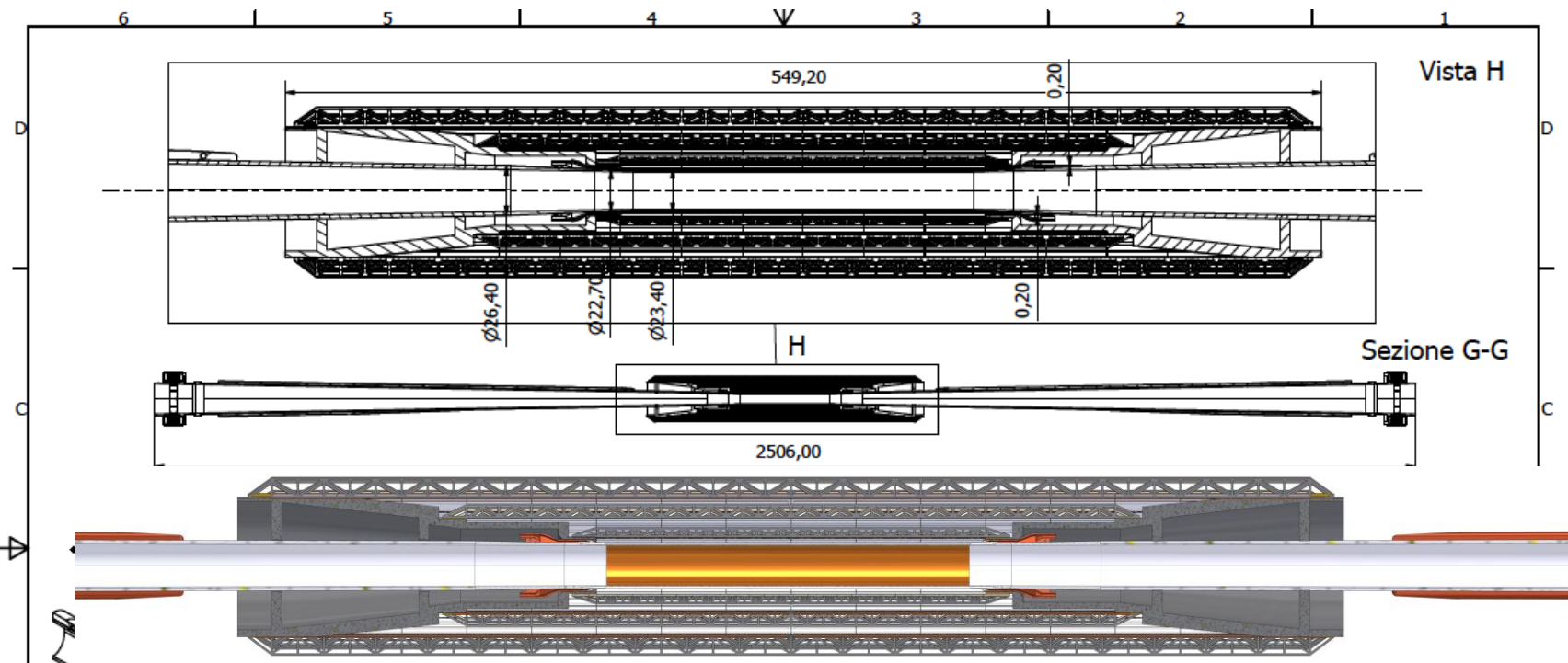
Layer 3
36 staves of 16 modules each

Lampshade geometry.
Charge symmetric track reconstruction

Total weight ~150 grams

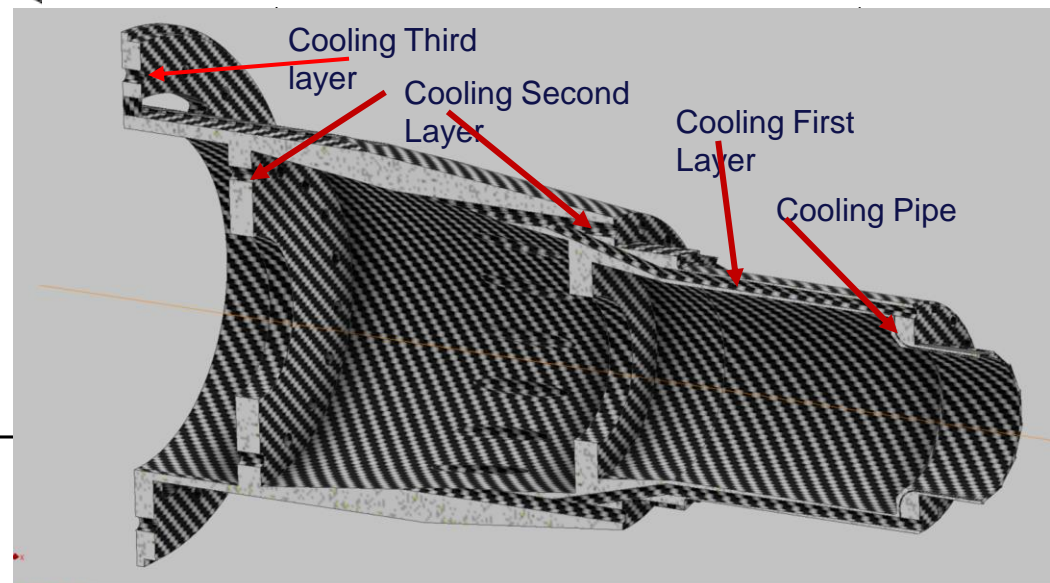
Total thickness 0.25% X₀

Power budget
~77 W



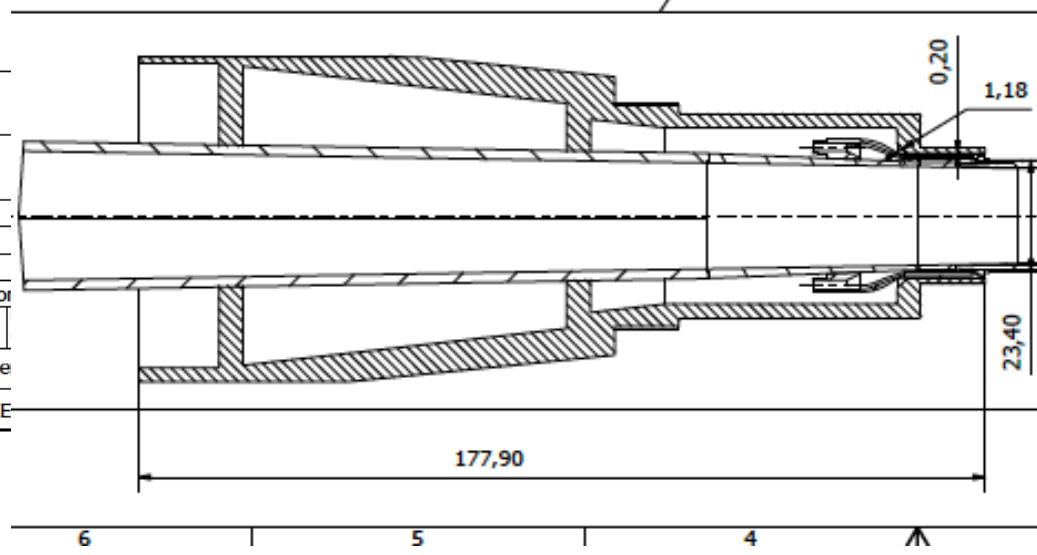
Inner vertex detector supporting conical structures on elliptical chamber
~450 grams

Engineered for air ducts and thermal isolation from the beam pipe during bakeout

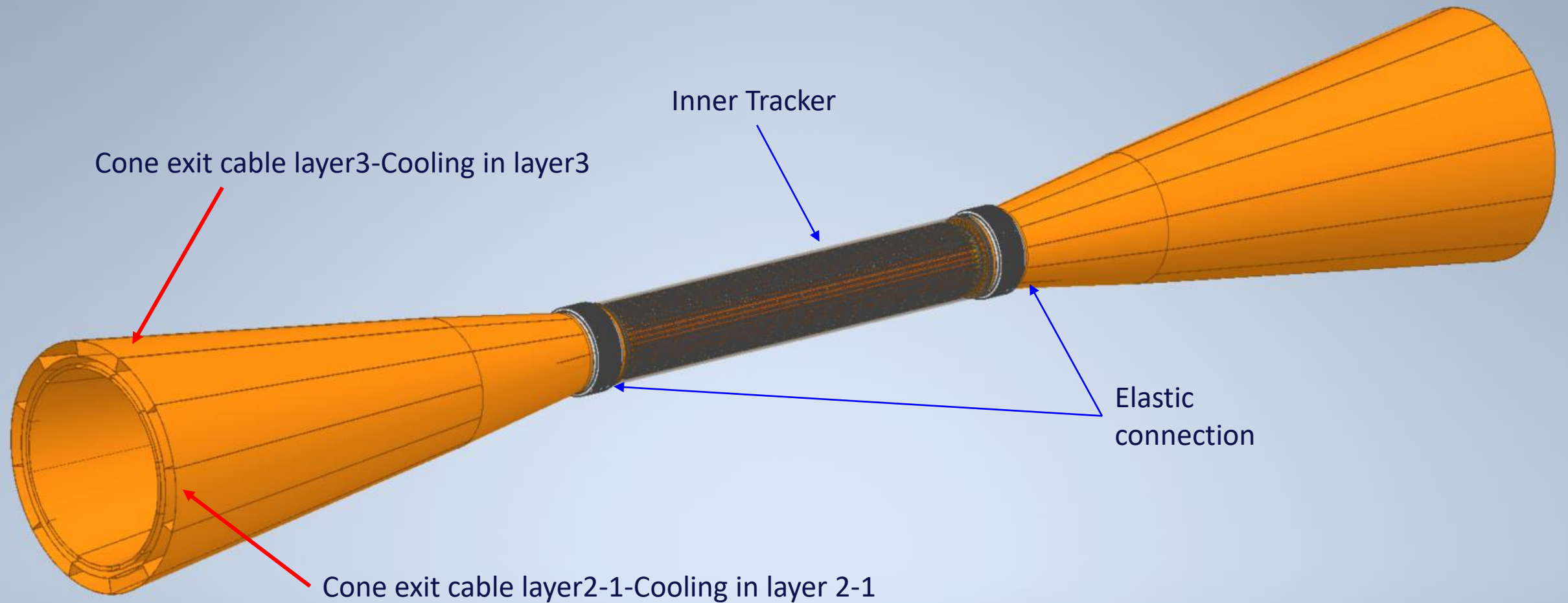


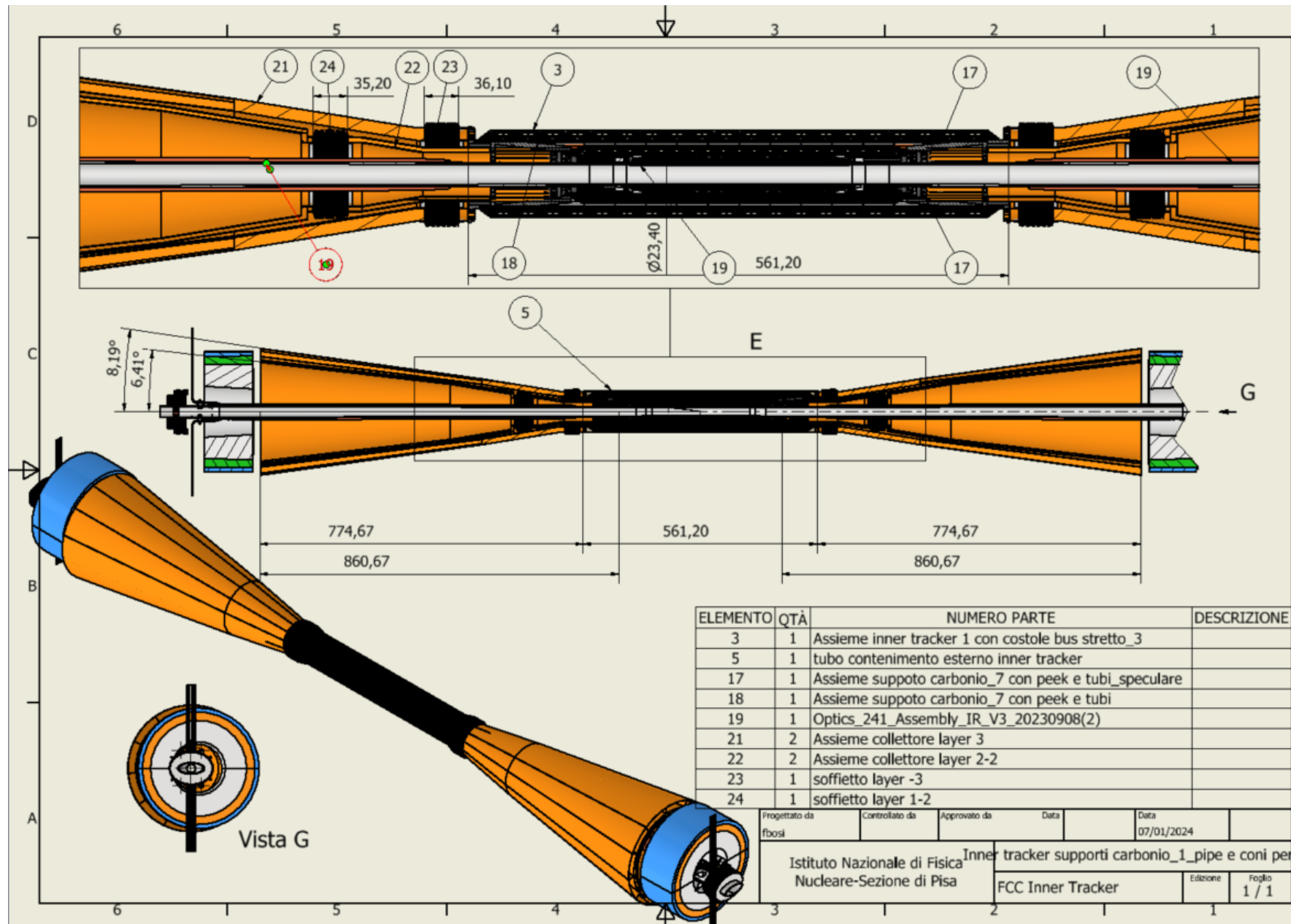
978,40

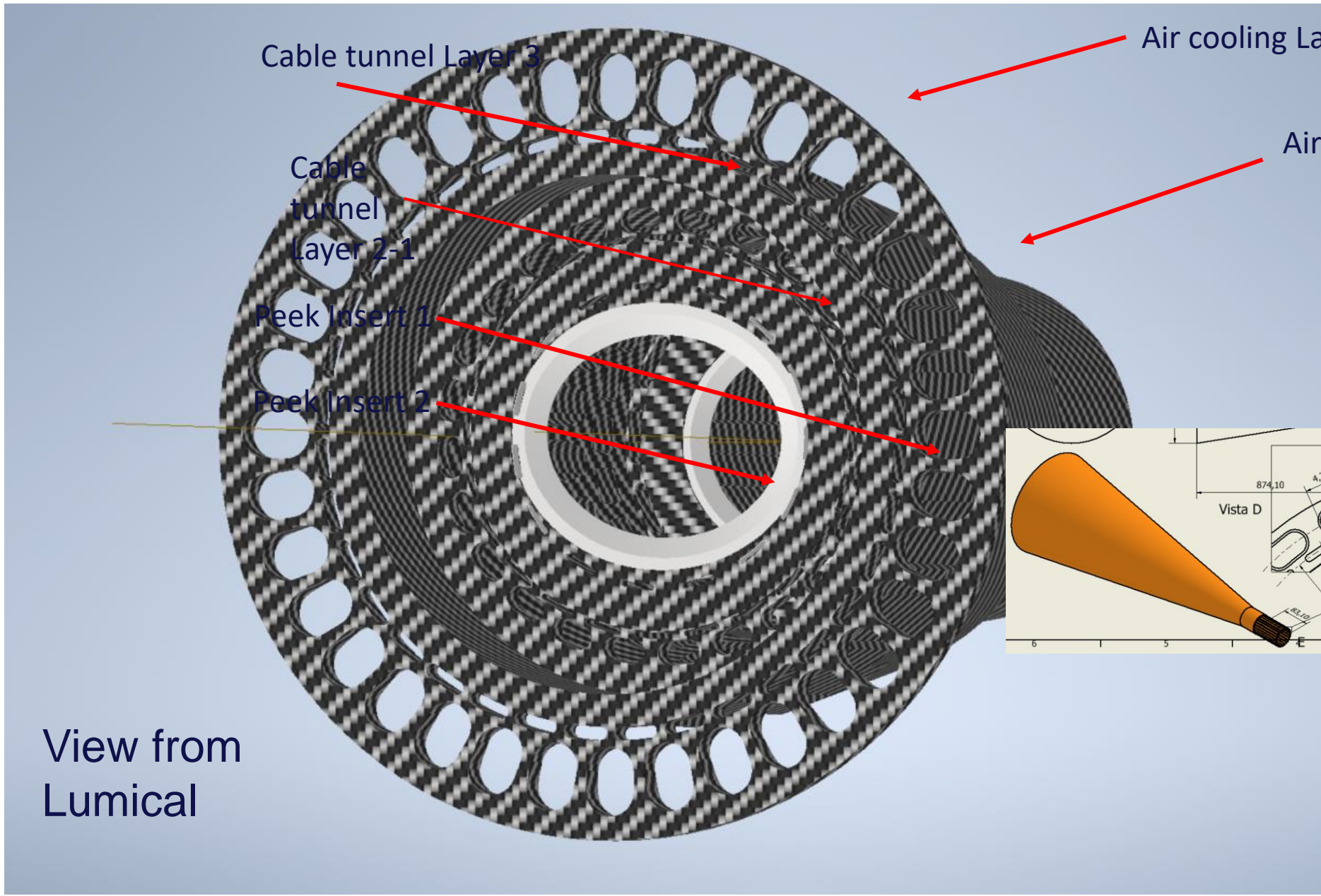
ELENCO PARTI		
NUMERO PARTE		
chamber_27012023		
Assieme inner tracker con supporti carboni		
Controllato da	Approvato da	Data
chamber_27012023+inne		
IDEA-INNER TRACKE		



Service cones for cooling and cables







Cable tunnel Layer 3

Air cooling Layer 3

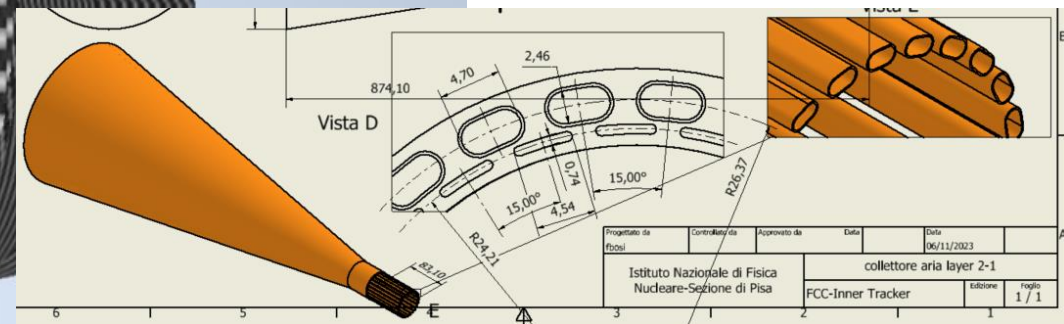
Cable tunnel layer 2-1

Air cooling Layer 2-1

Peek Insert 1

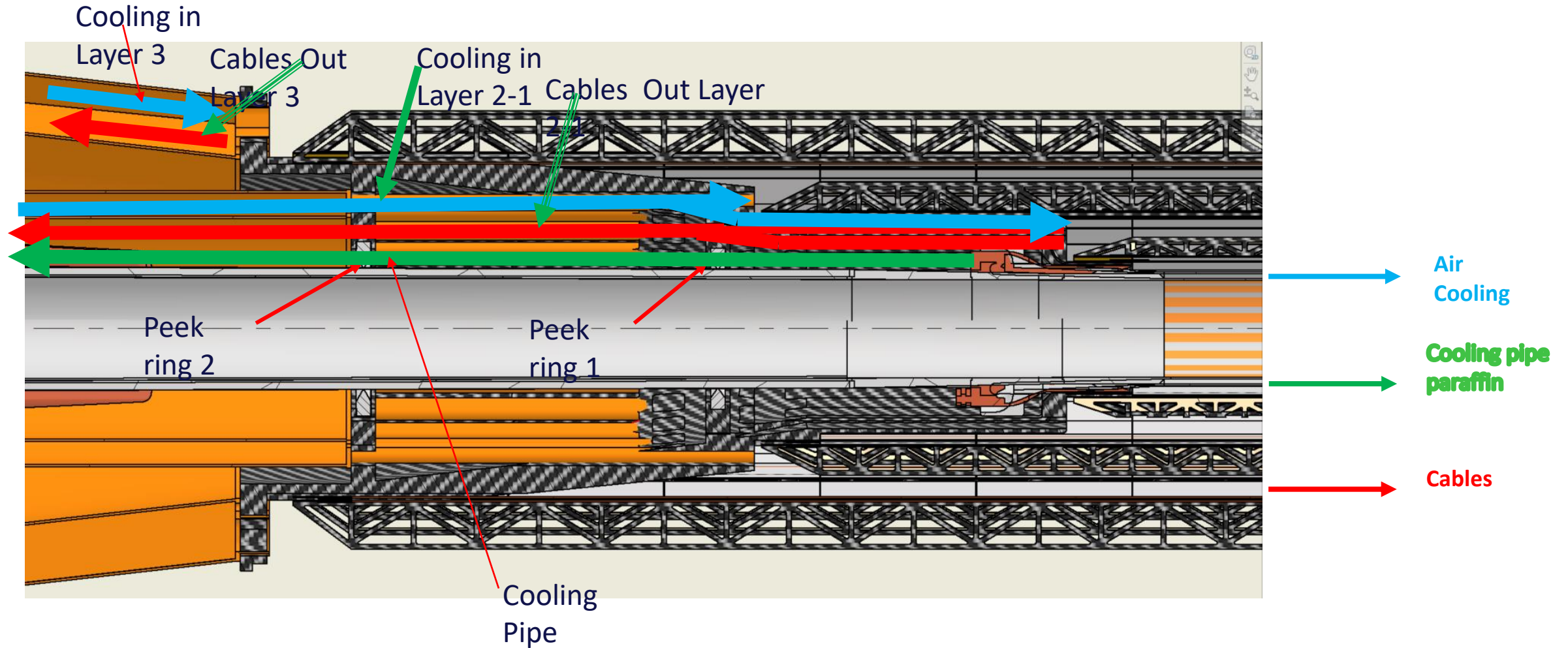
Peek Insert 2

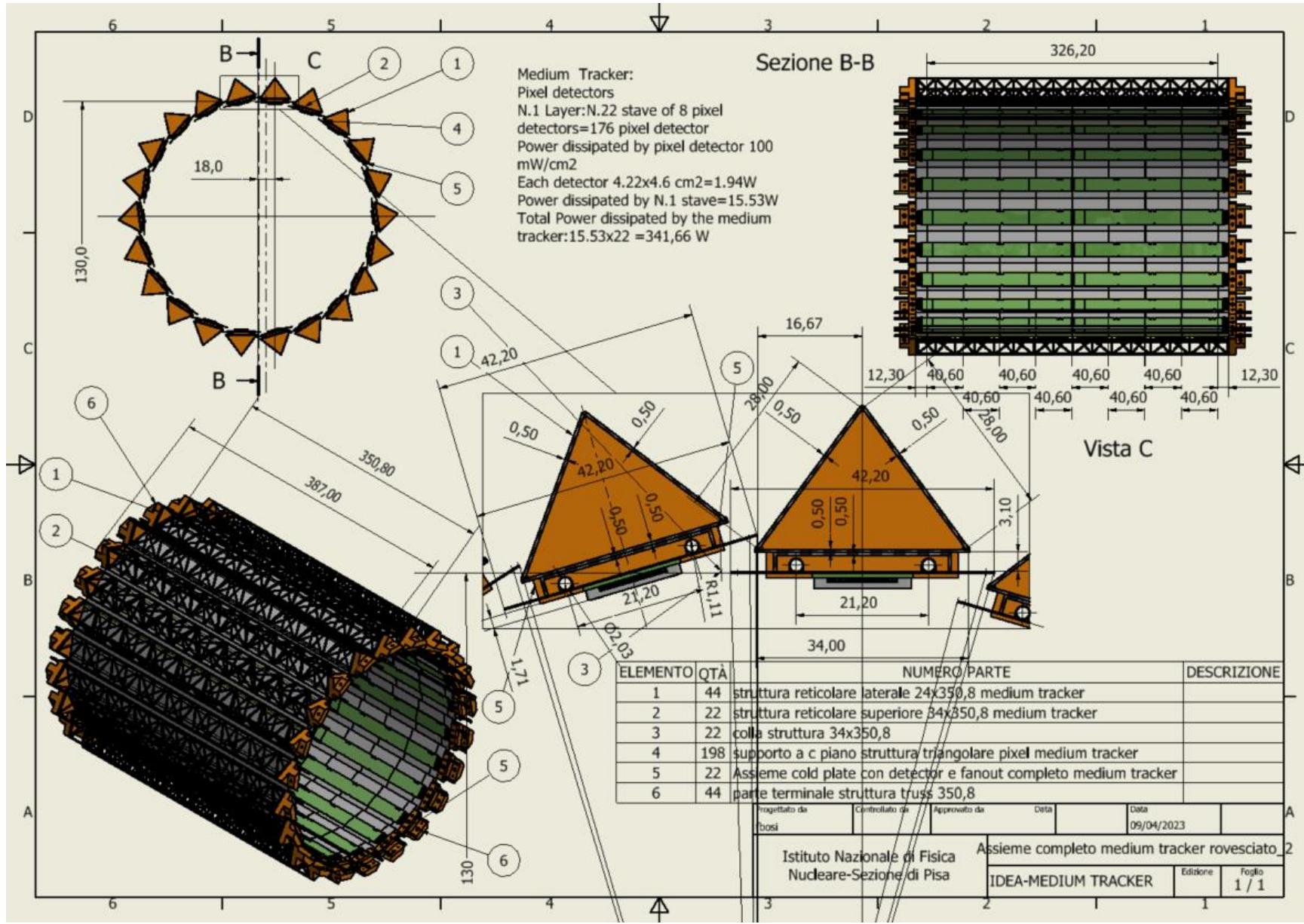
View from Lumical



See C. Turrioni talk on Vertex Air cooling

Integration with beam pipe cooling manifold





Middle Vertex Barrel
At 13 cm radius

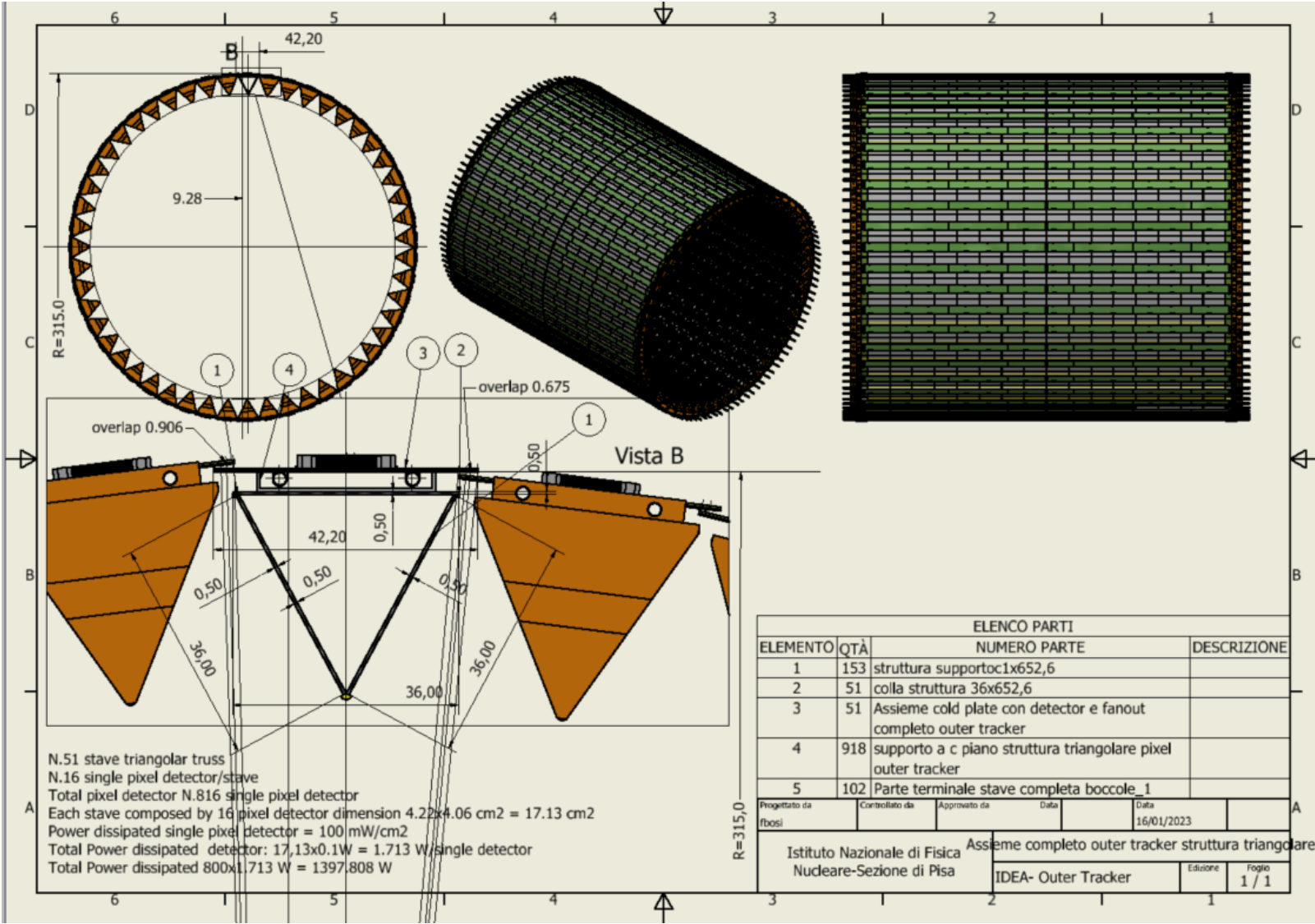
22 staves of 8 modules each.

Lightweight reticular support structure (ALICE/Belle-II like)

Readout chips either side

Power budget
~342 W

Total weight ~1 kg
 Water cooled (2 pipes of 2 mm diameter)



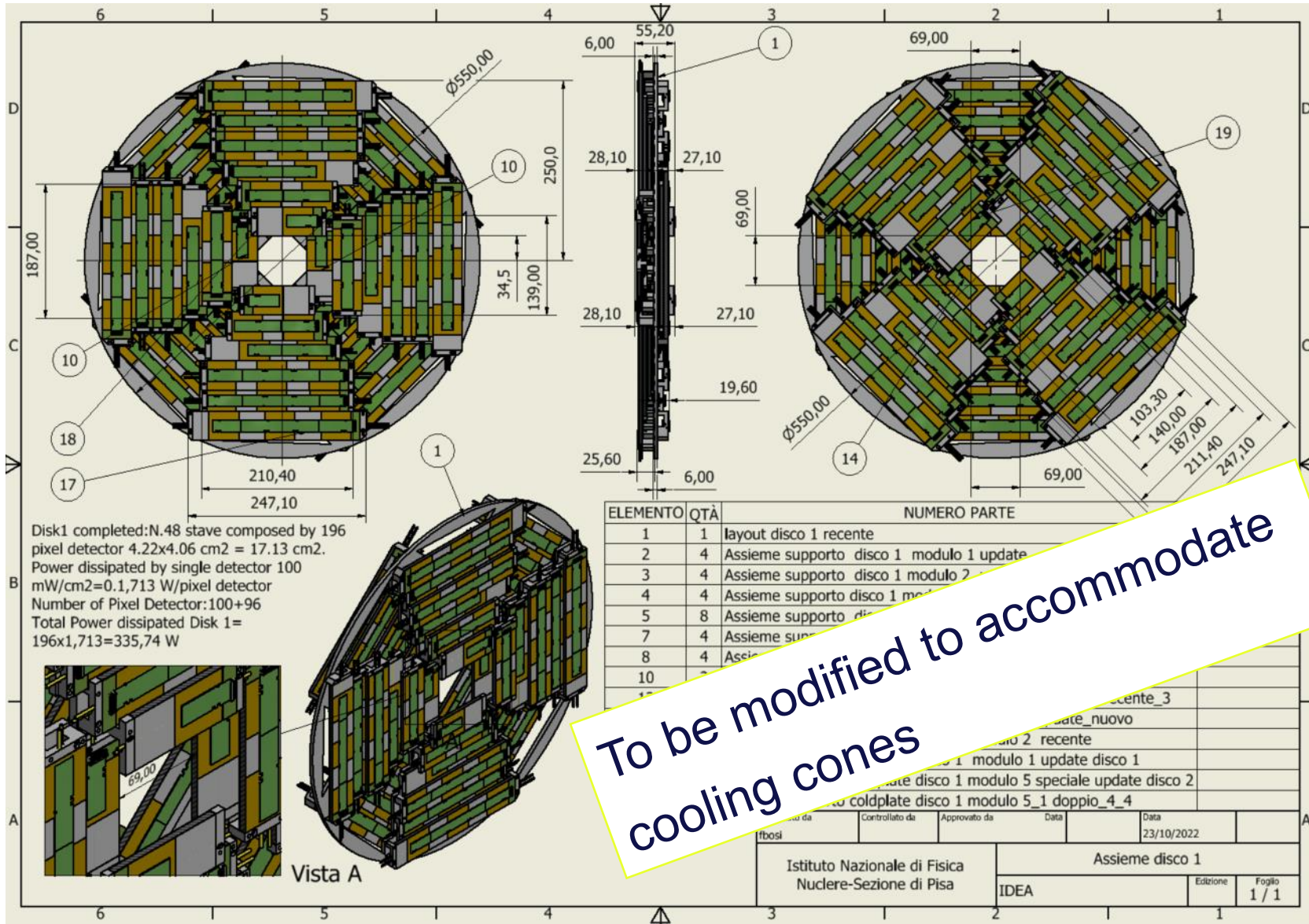
Outer Vertex Tracker Barrel
At 31.5 cm radius

51 staves of 16 modules each

Lightweight reticular support structure (ALICE/Belle-II like)

Total weight ~3.7 kg
 Readout chips either side
Power budget ~1400 W

Water cooled (2 pipes of 2 mm diameter)



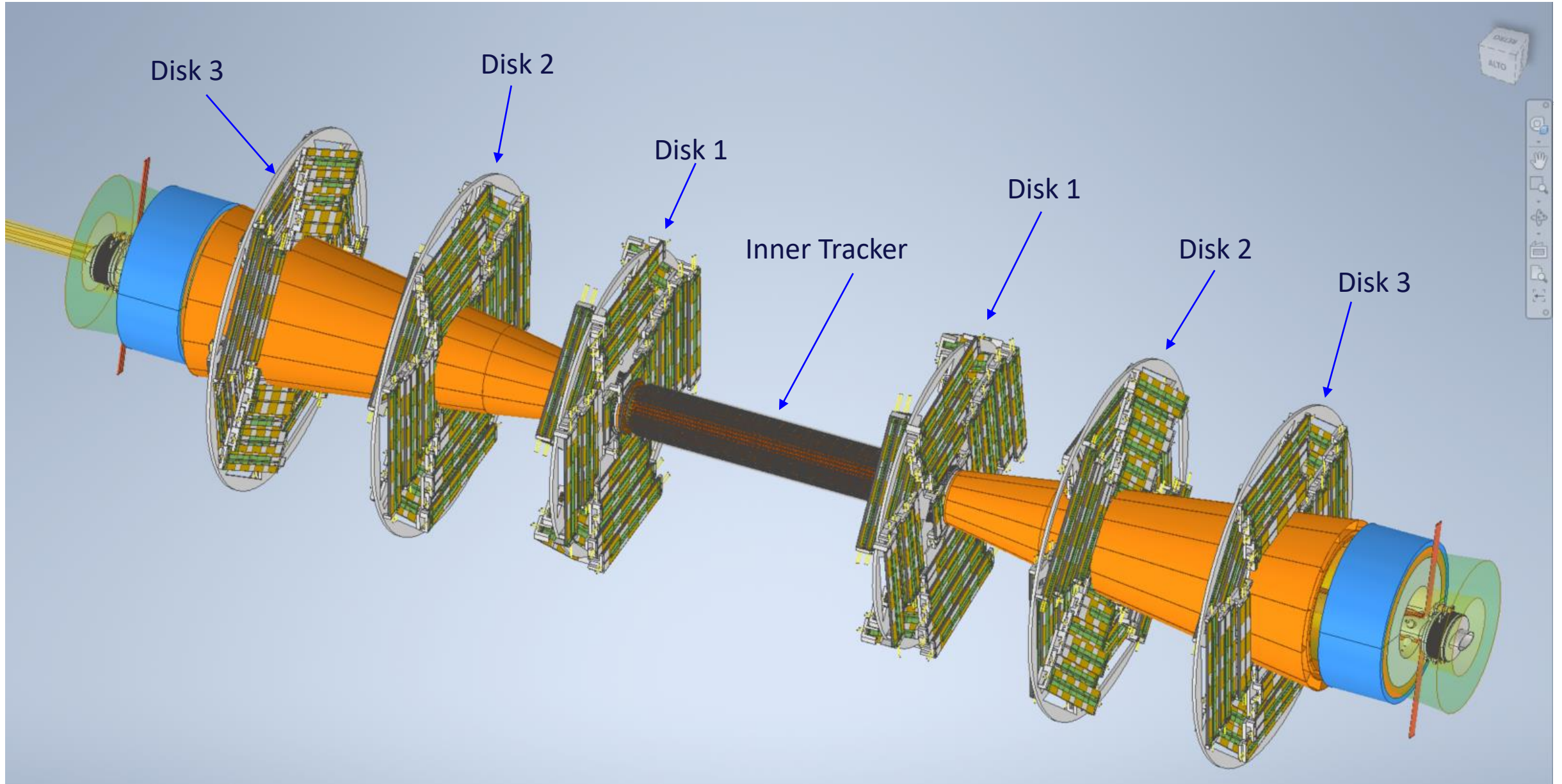
Outer Vertex Tracker Disk 1
 2 sides (front and back) each with 4 petals.

One petal is made of different staves of overlapping modules

Total modules per disk: 196
 Total weight ~850 grams
 Power budget ~ 336 W

Cooling using 1 water pipe (2 mm diameter)

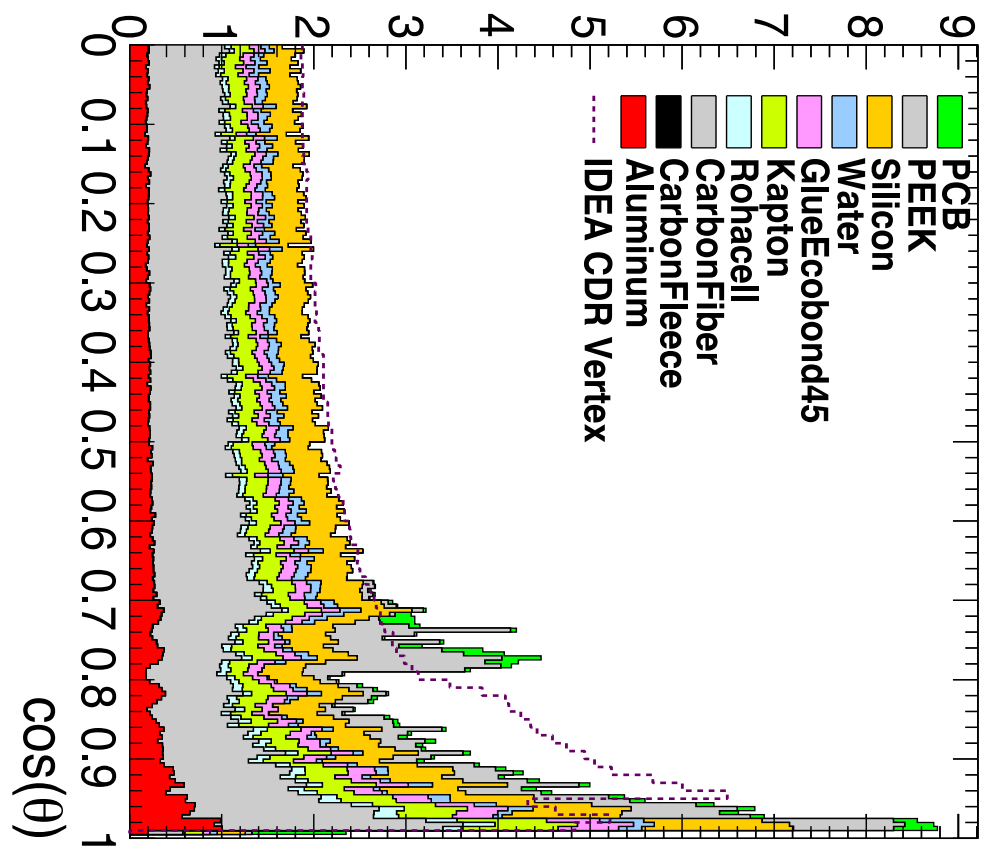
Similar geometry for the other two disks



Simulated material budget

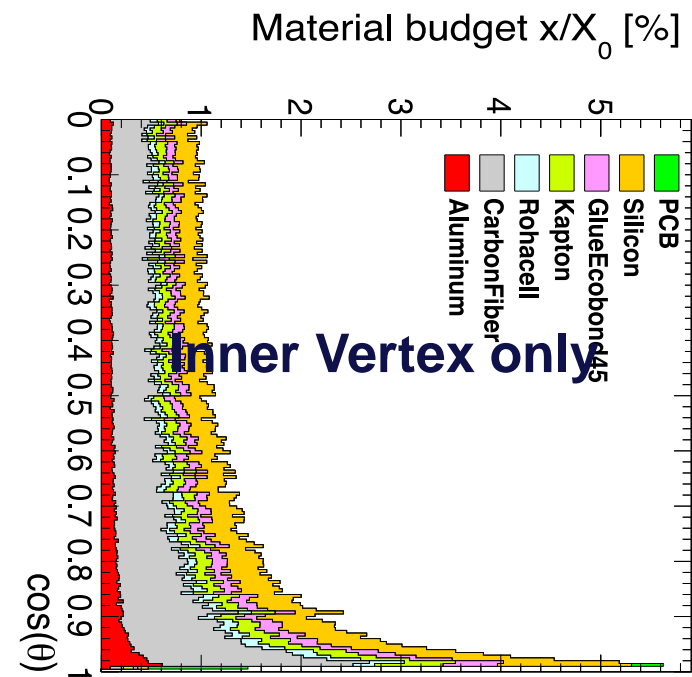
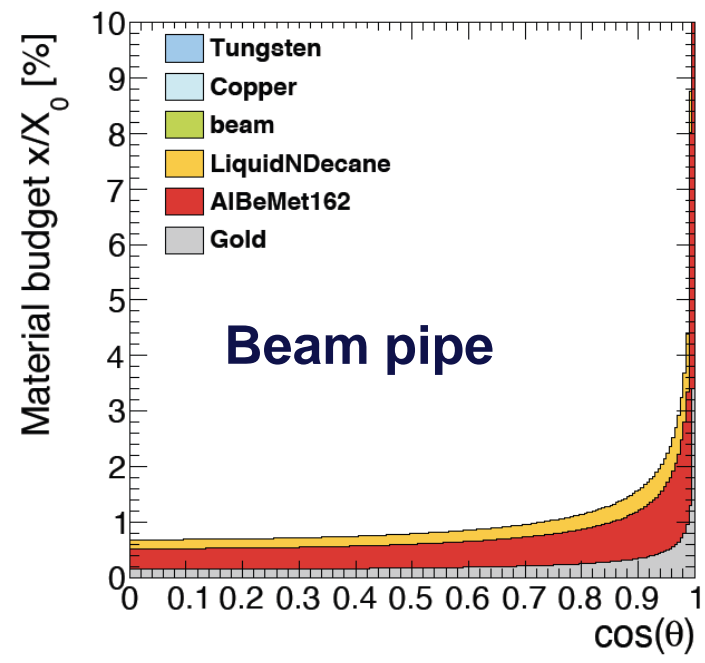


Material budget x/X_0 [%]



See [A. Ilg talk](#)

In agreement with CAD estimates
 Smaller X/X_0 wrt IDEA CDR estimates even including power and readout cables in the sensitive region
 Silicon only ~15% of the total



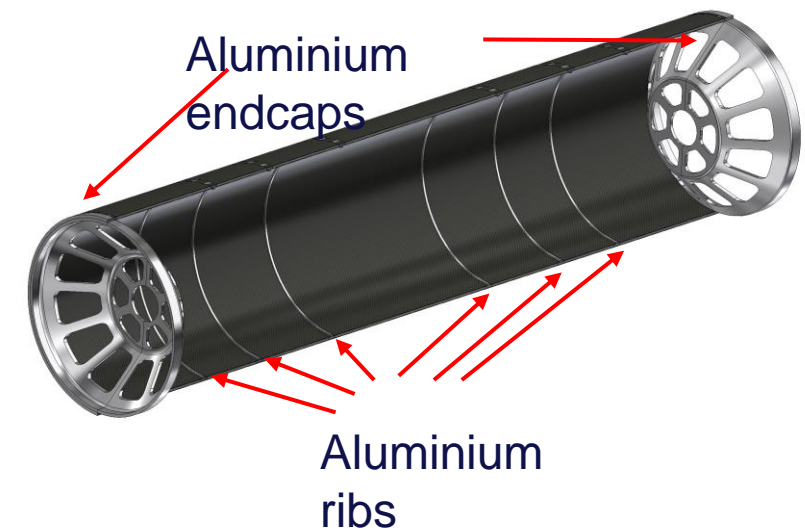
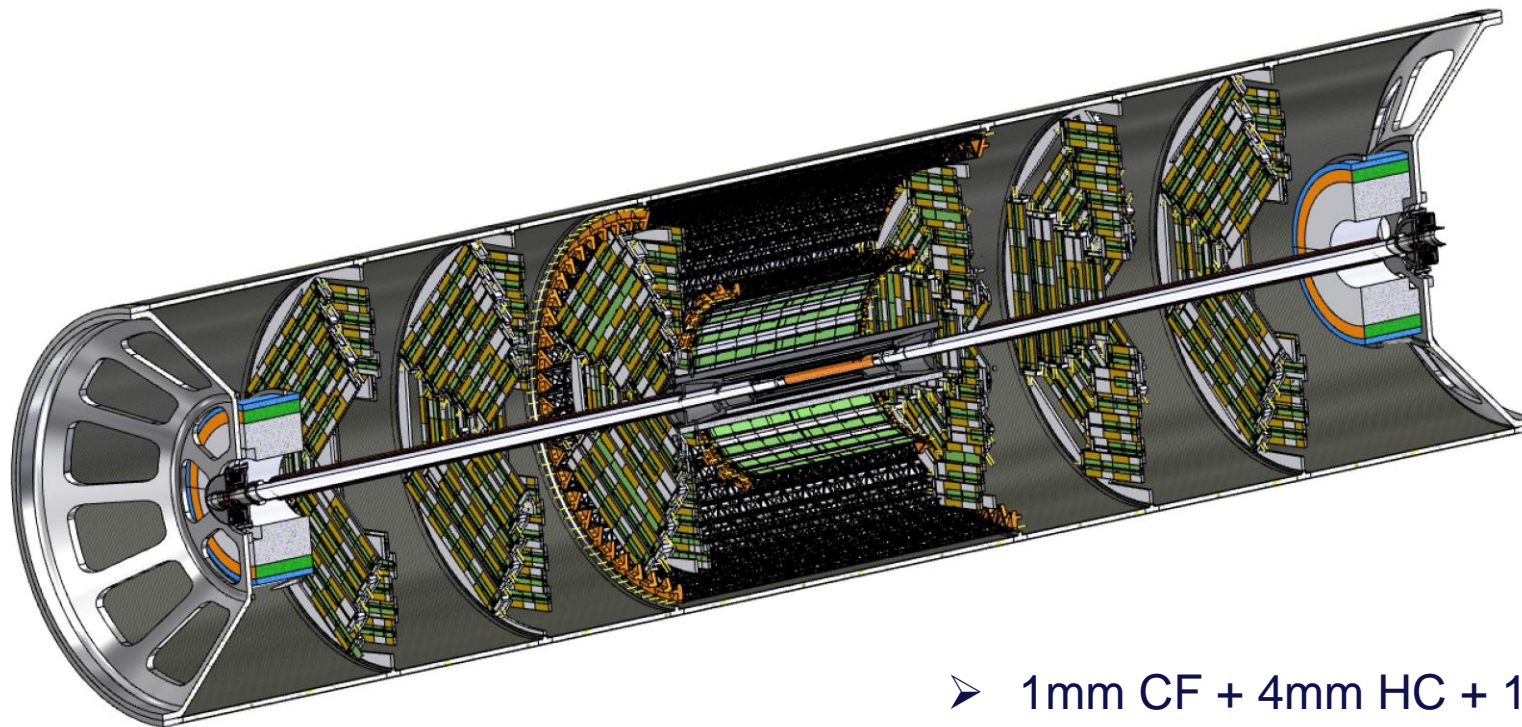
Support cylinder

See [talk from F. Franesini](#)

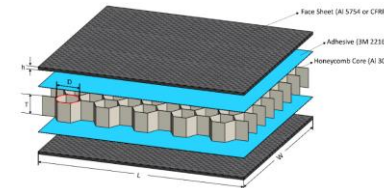


All elements in the interaction region (Vertex and LumiCal) are mounted rigidly on a support cylinder that guarantees mechanical stability and alignment

- Once the structure is assembled it is slid inside the rest of the detector



➤ 1mm CF + 4mm HC + 1mm CF



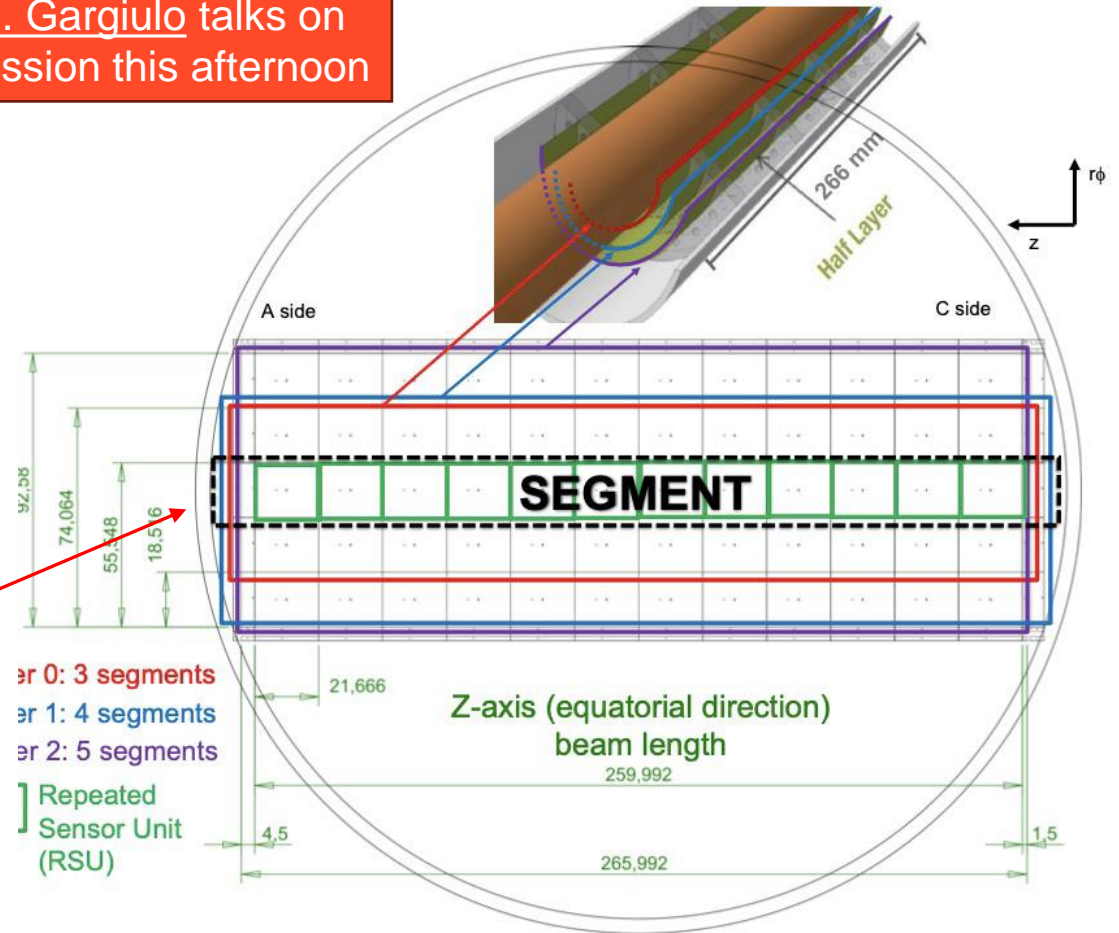
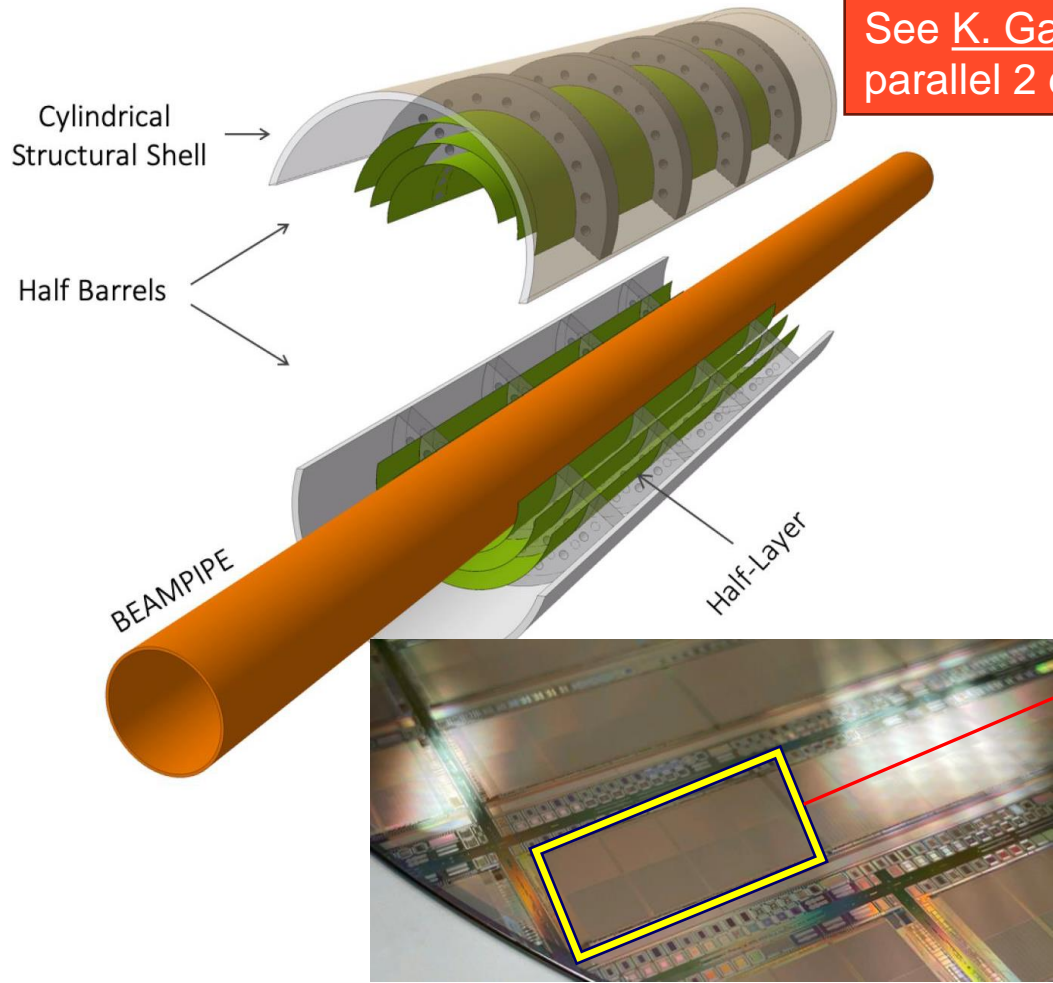
General integration

M. Boscolo, F. Palla, F. Franesini, F. Bosi and S. Lauciani, Mechanical model for the FCC-ee MDI, EPJ Techn Instrum **10**, 16 (2023).
<https://doi.org/10.1140/epjti/s40485-023-00103-7>



see A. Gaddi talk

See [K. Gautam](#) and [C. Gargiulo](#) talks on parallel 2 detectors session this afternoon



ALICE ITS3 inner vertex inspired design – issues

(0.2 % X/X_0 material budget – 5 times less than the Mid-Term one)

After fruitful discussions with **C. Gargiulo**, **A. Junique**, **G. Aglieri Rinella**, **W. Snoeys**

Issues – I

ALICE smaller radius will be 18 mm (beam pipe 16 mm)

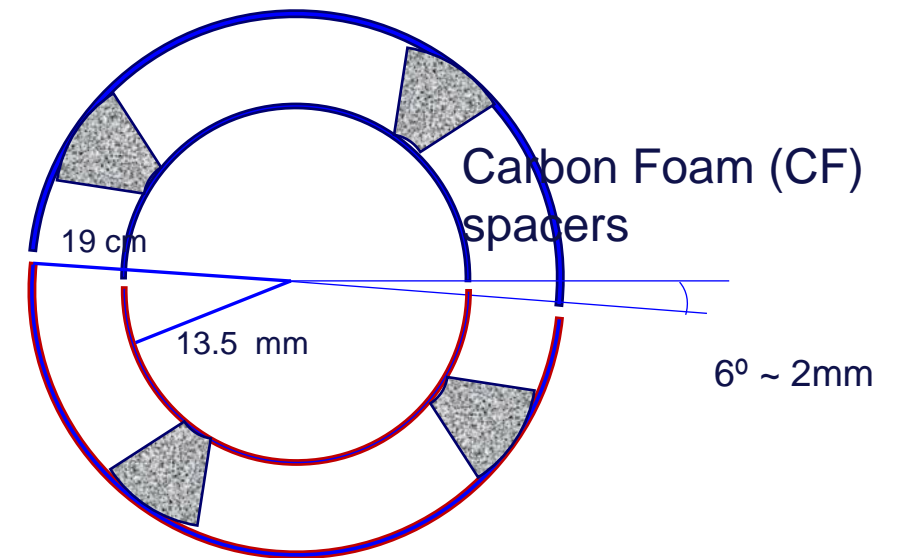
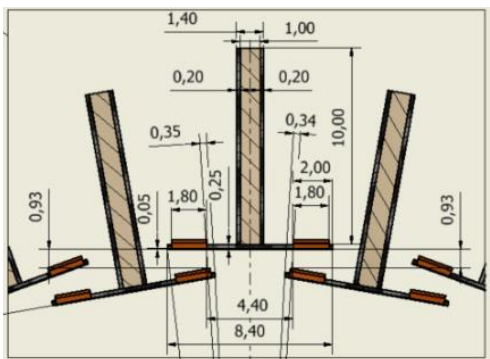
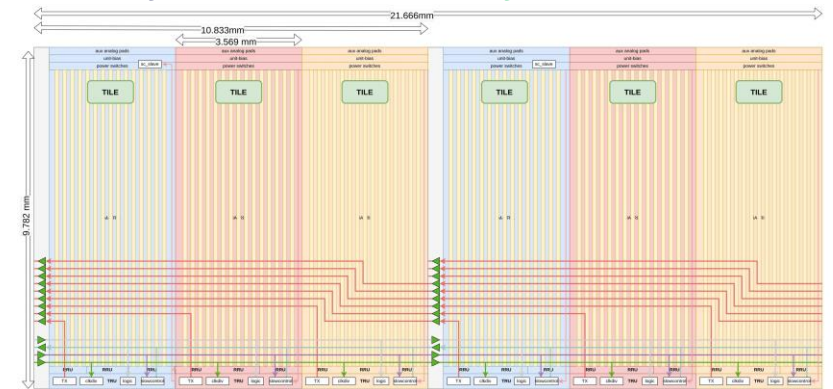
- Needs to demonstrate bent MAPS with 13.5 mm radius works electrically – **mechanically OK**

Active pixels 95% of covered area (chip service zones)

- Which impact has on physics?
- Cannot overlap sensors as in “traditional” layouts in same layer**
- Can be recovered in ϕ by rotating two layers at different radii

If same angular coverage for all layers is sought

- Then needs to 2 stitched structures in z for outer layers



ELECTRICAL UNITS

MOSAIX - Top Integration Diagram

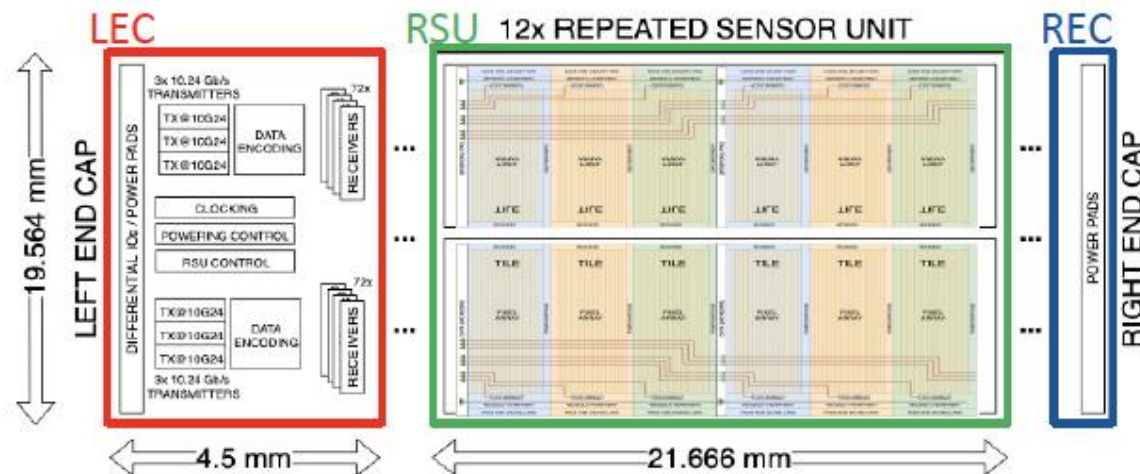
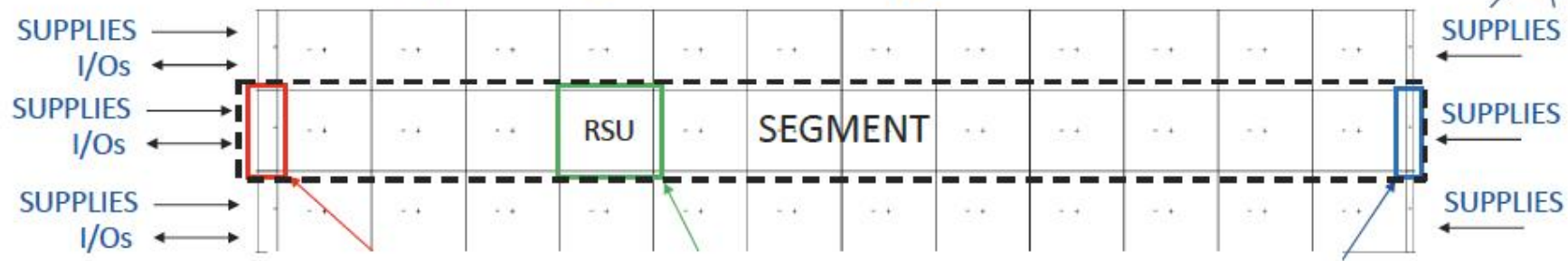
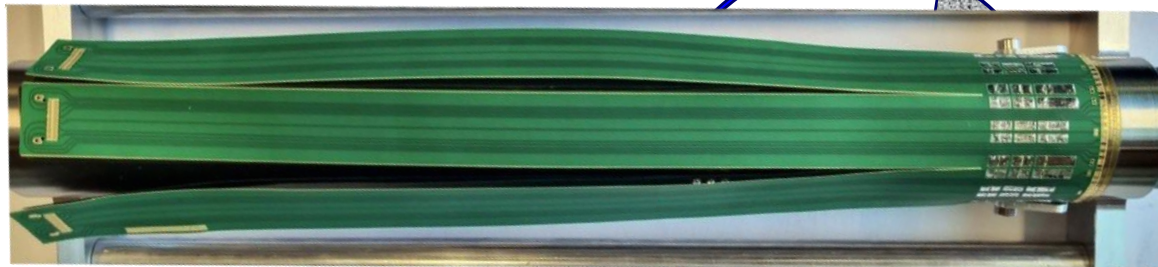
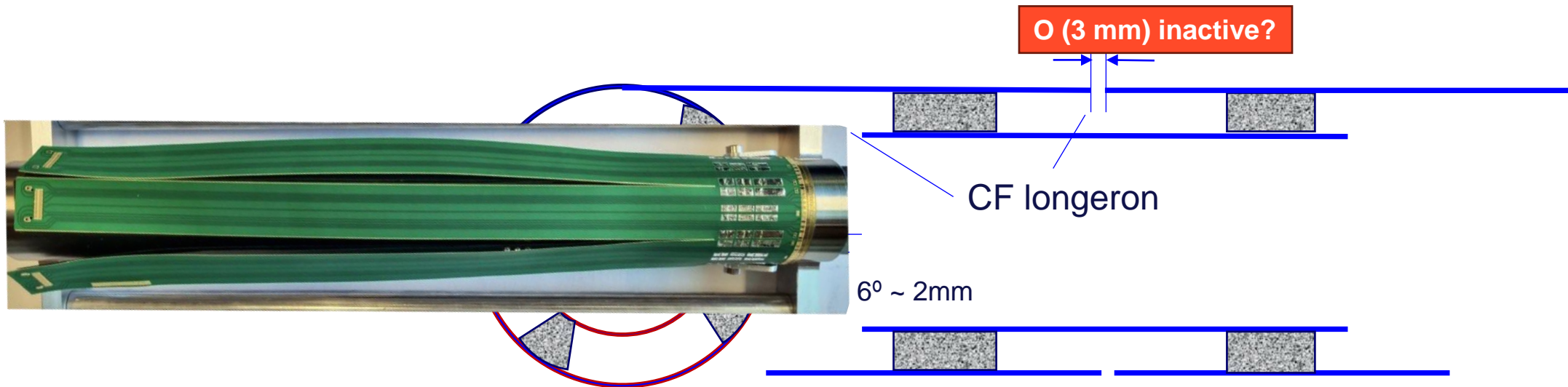
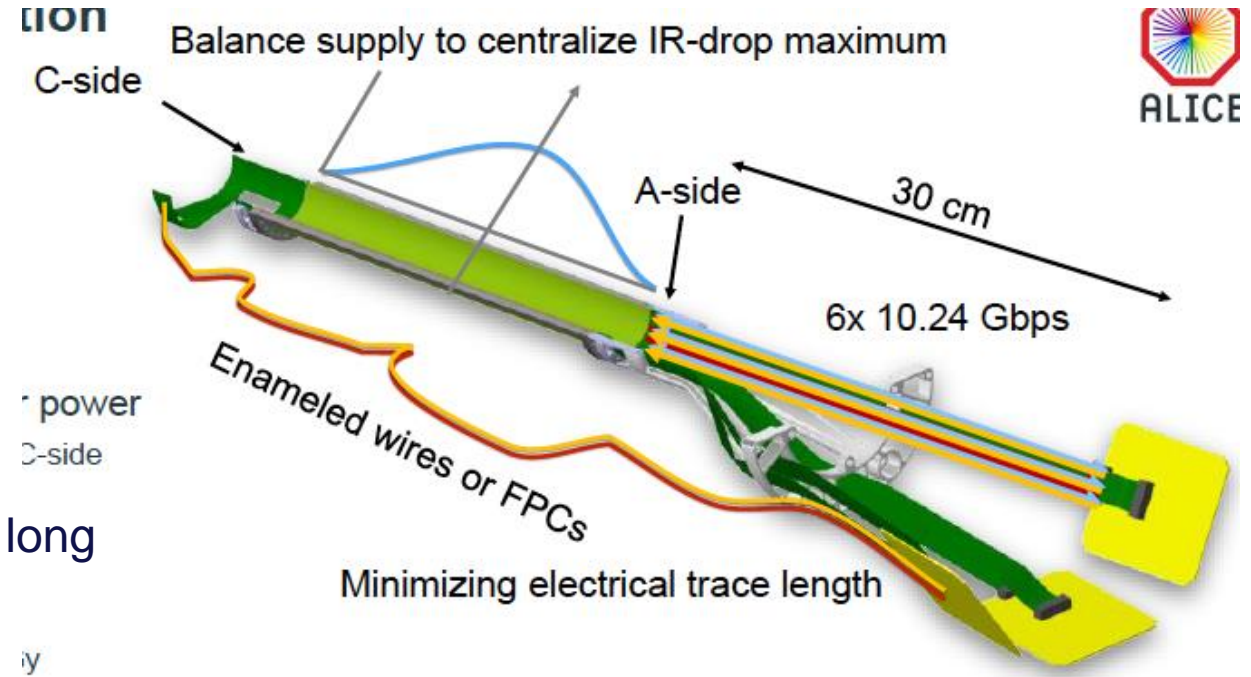


Figure 3.34: Block diagram of the sensor segment.

Issues – II

- **2nd layer @ higher radius**

- Rotated to recover ϕ dead zones of 1st layer
- 27 cm long in z → needs two stitched 13.5 cm long
- Possible to power on one side only
- Cannot overlay two stitched structures
 - Few mm inactive zones

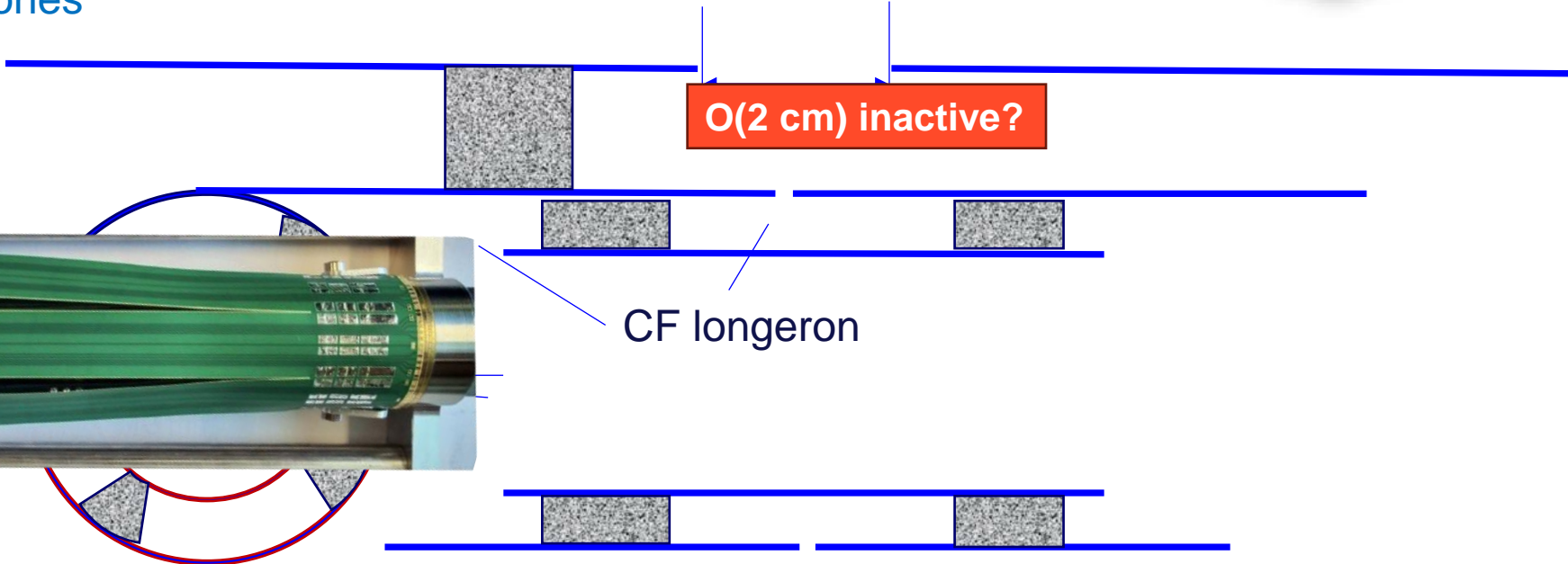
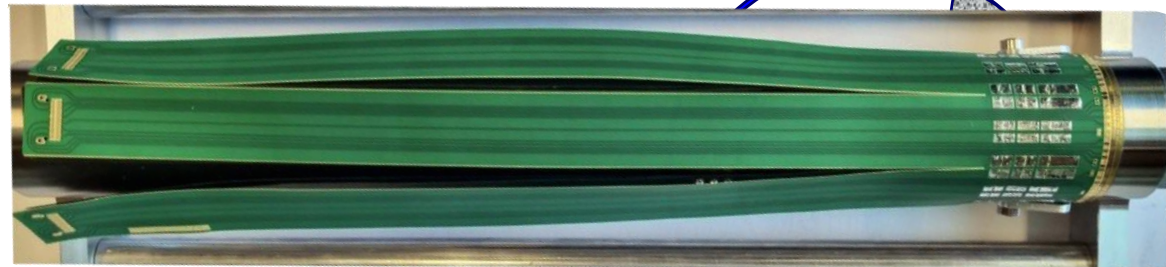
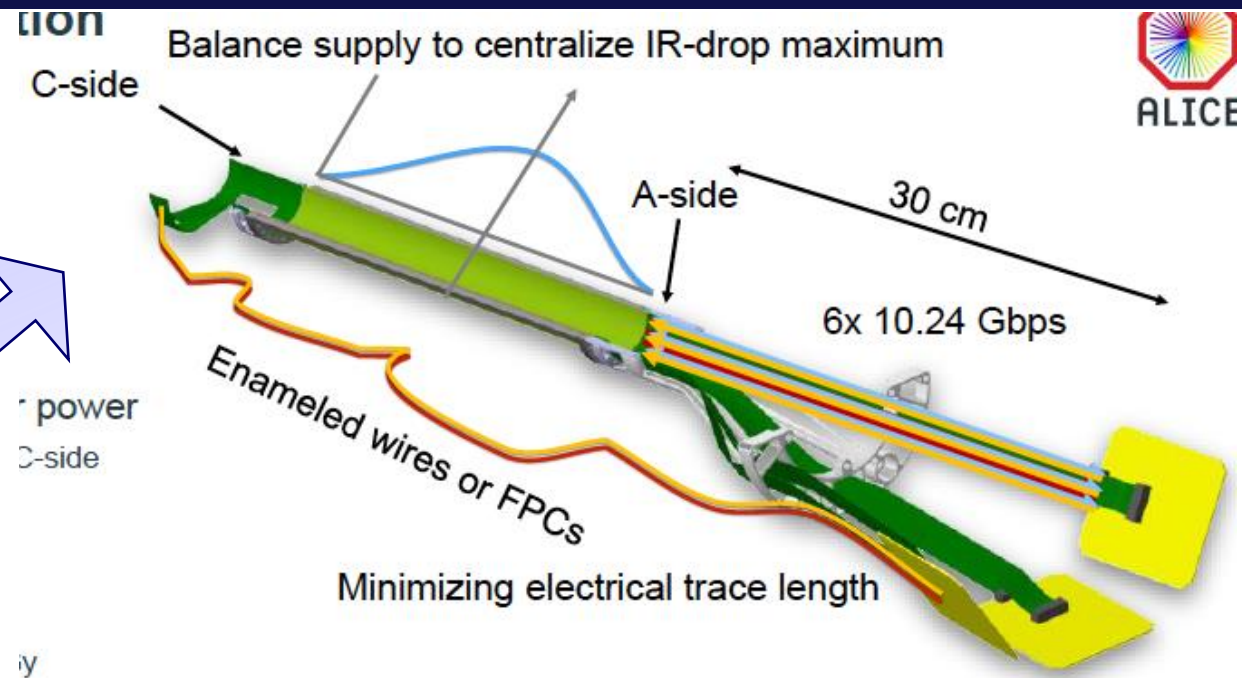
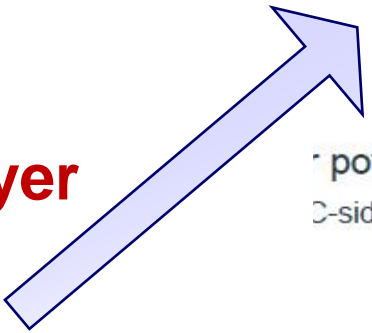




Issues – III

• Problems in z for 3rd layer

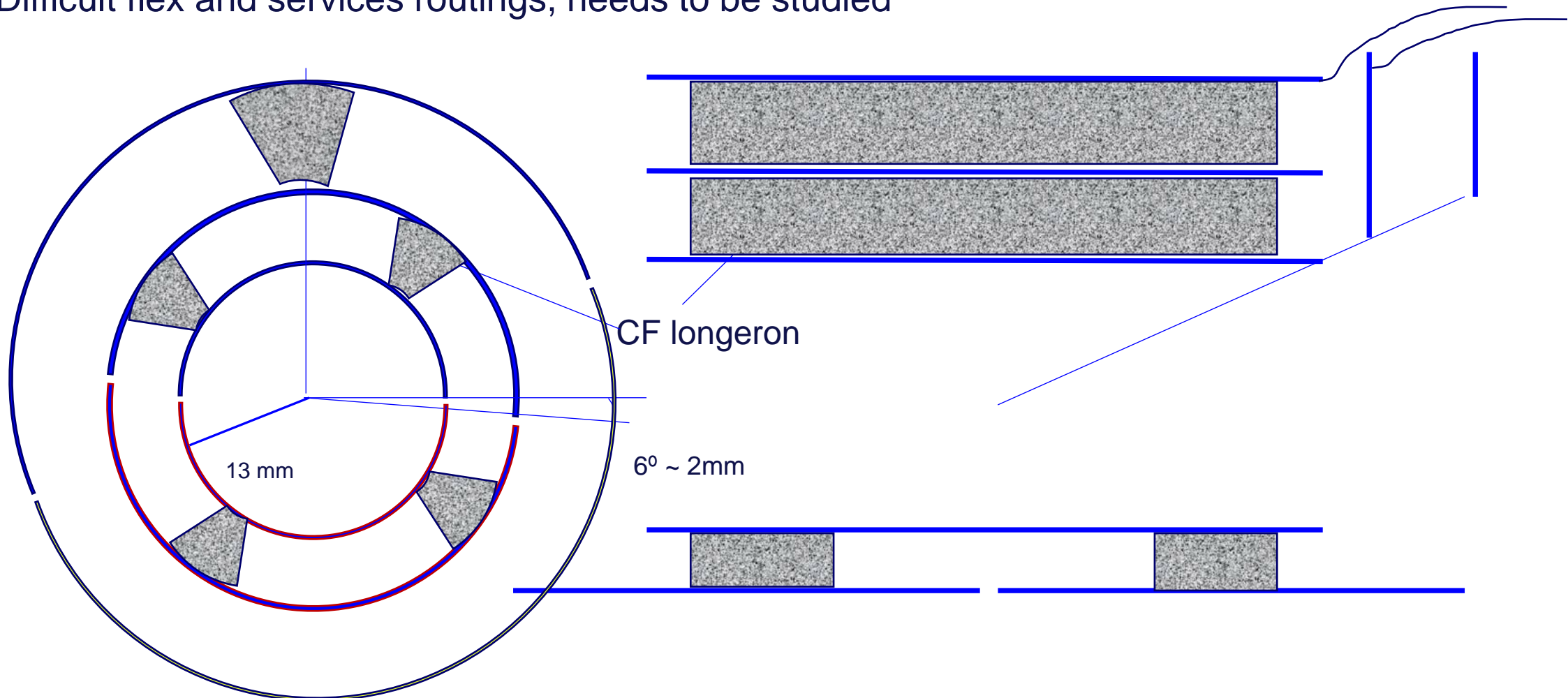
- 2x25 cm long in z
- Need power on both sides
- Flex circuit length ~ O(1 cm)
- Cannot overlap the two sides
- Large O(few cm) dead zones



Issues – IV

Alternative layout using one same length barrel section plus disks?

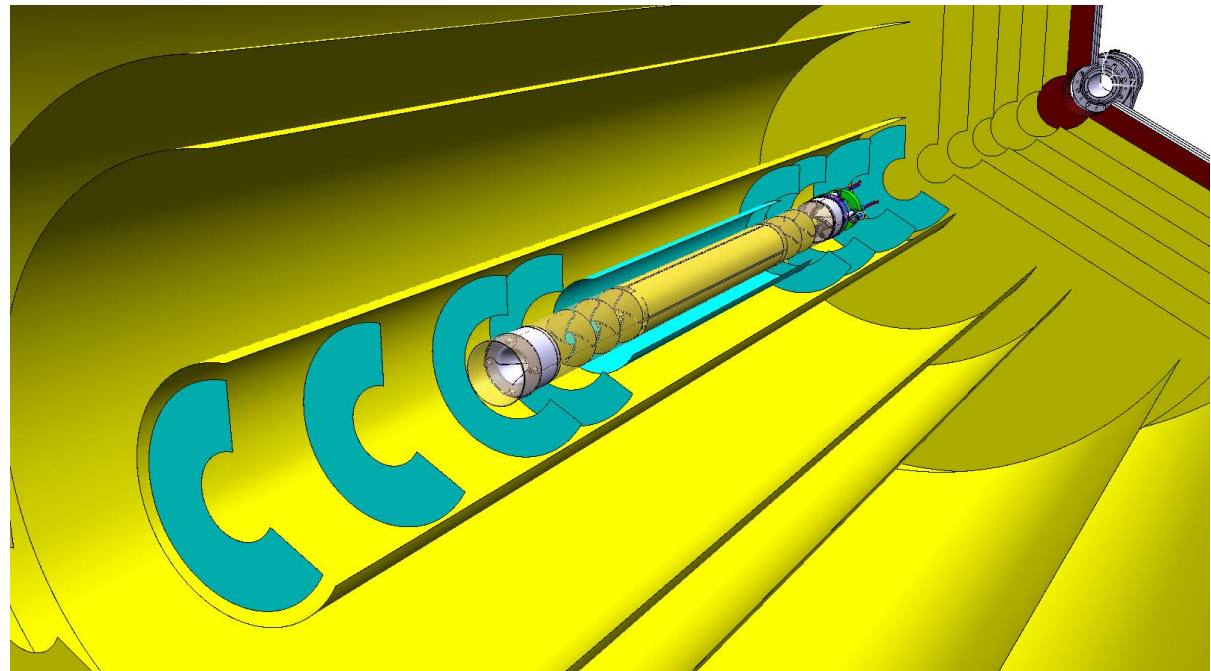
- Difficult flex and services routings, needs to be studied



Issues – V

Even more aggressive put everything in beam pipe with a secondary vacuum (ALICE IRIS) needs to address (and solve!) several other problems

- Beampipe aperture
- Vacuum
- Resistive wall effects (heating – O(60 Watt for 5 mm radius @ the Z) – and beam instability)
- Cooling and services routing
- ...



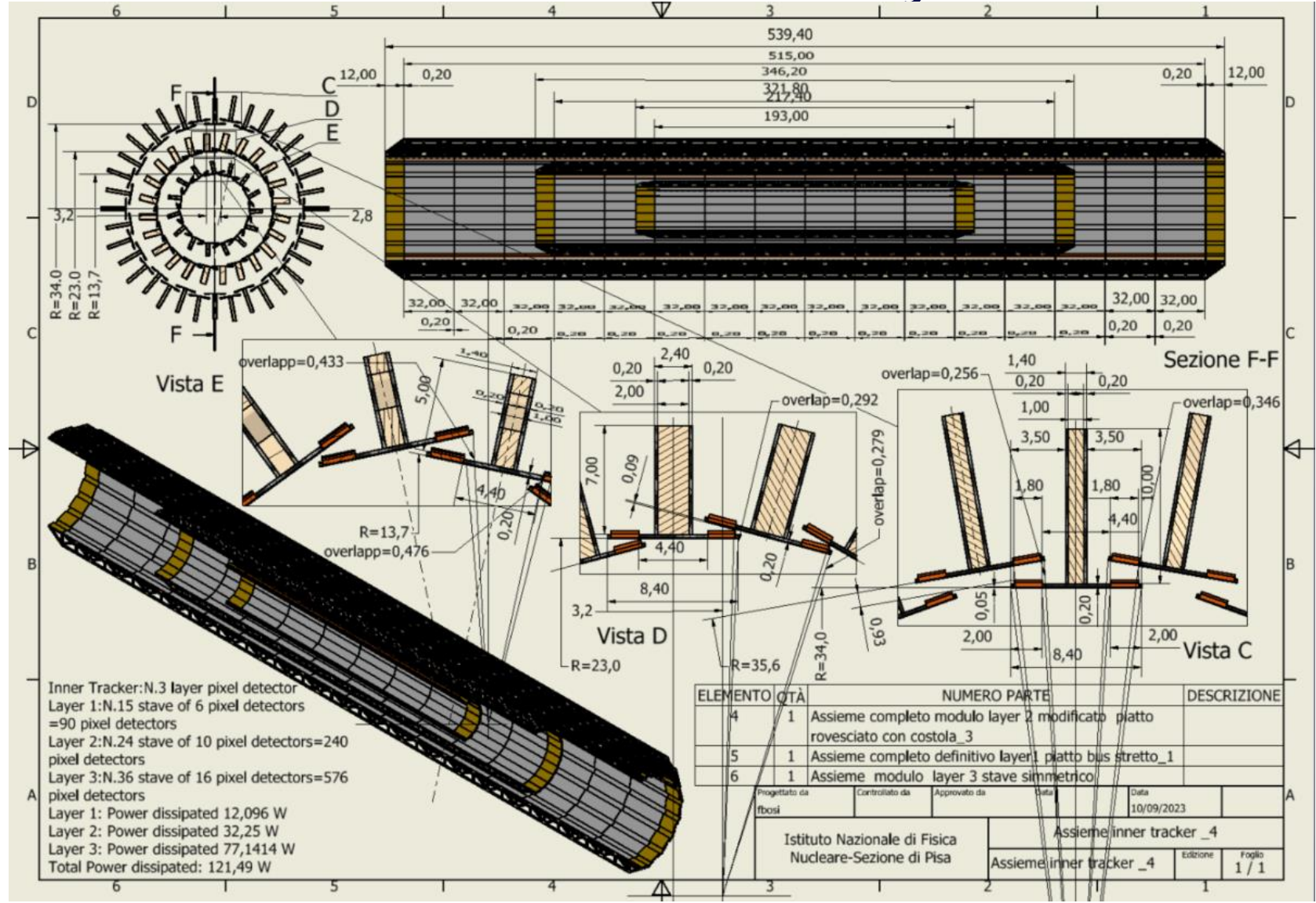
Conclusions

- **A layout of the Vertex Detector of IDEA (and ALLEGRO) has been engineered**
 - Uses low power, thin (50 μm) MAPS technology
 - Integration with the machine detector elements developed
 - Services integration and cooling are being finalised
 - Material budget kept at the level of 0.3 % X/X_0 per layer (Silicon only 15% of the total)
- **A much lighter concept with curved and stitched MAPS is starting**
 - Issues to be solved to gain full detector efficiency
 - Might be of interest for dedicated experiment for heavy flavours



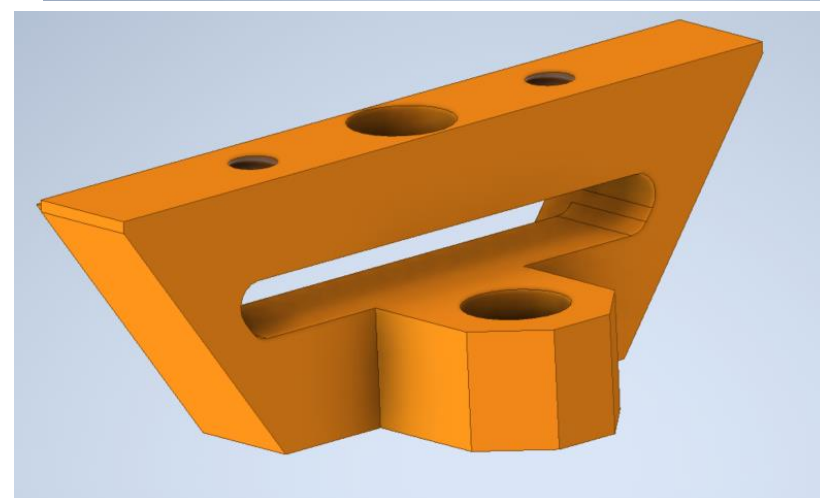
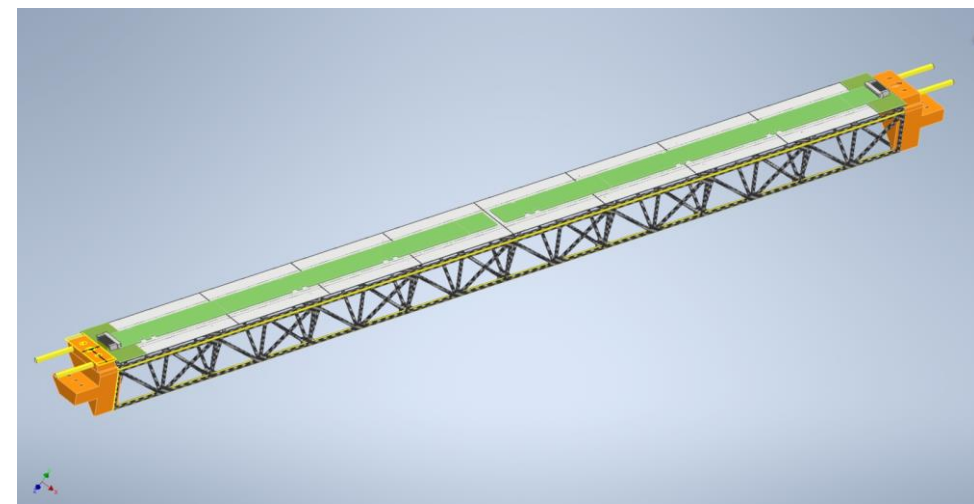
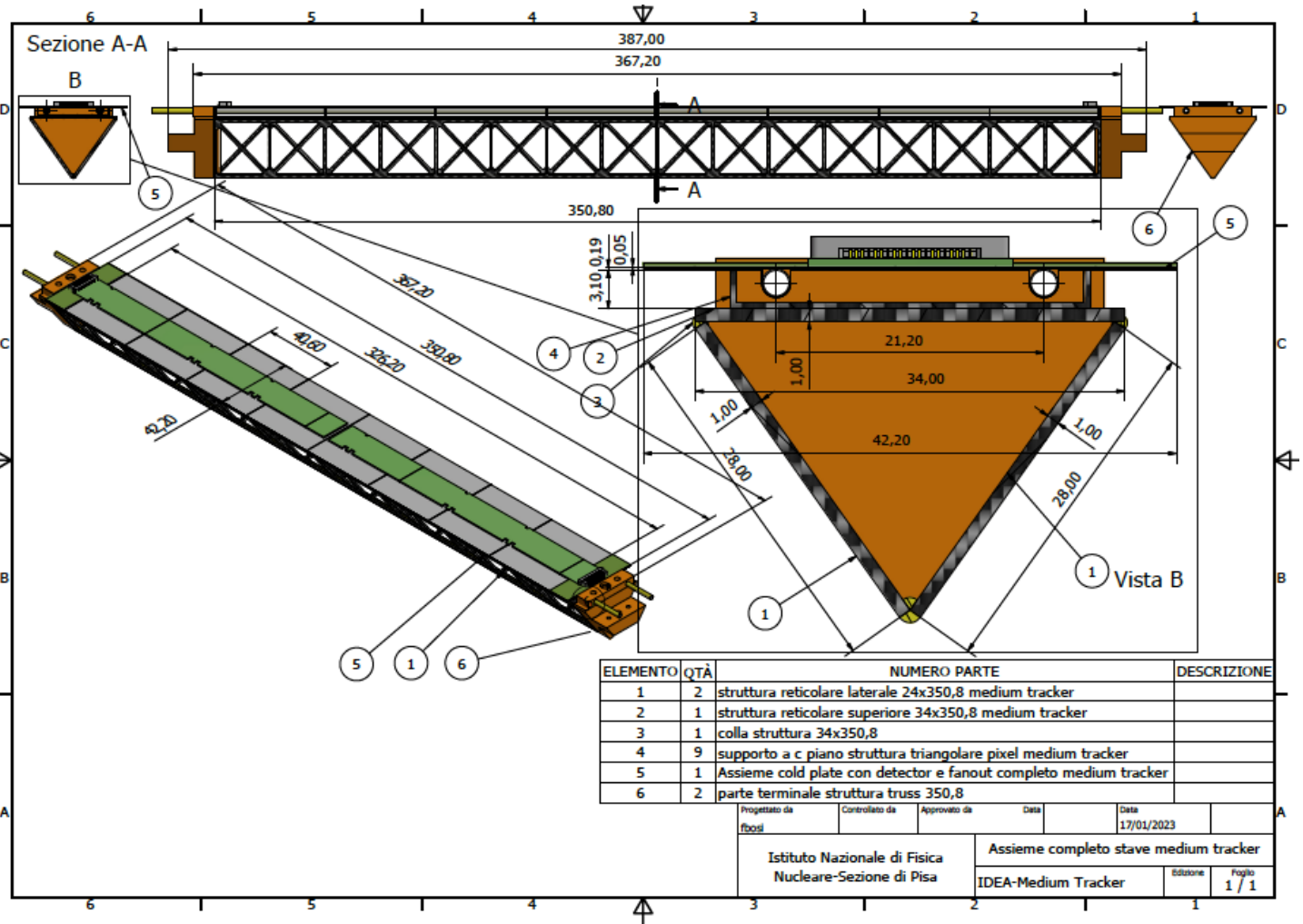
Thank you
for your attention.

Overall Inner Vertex layout

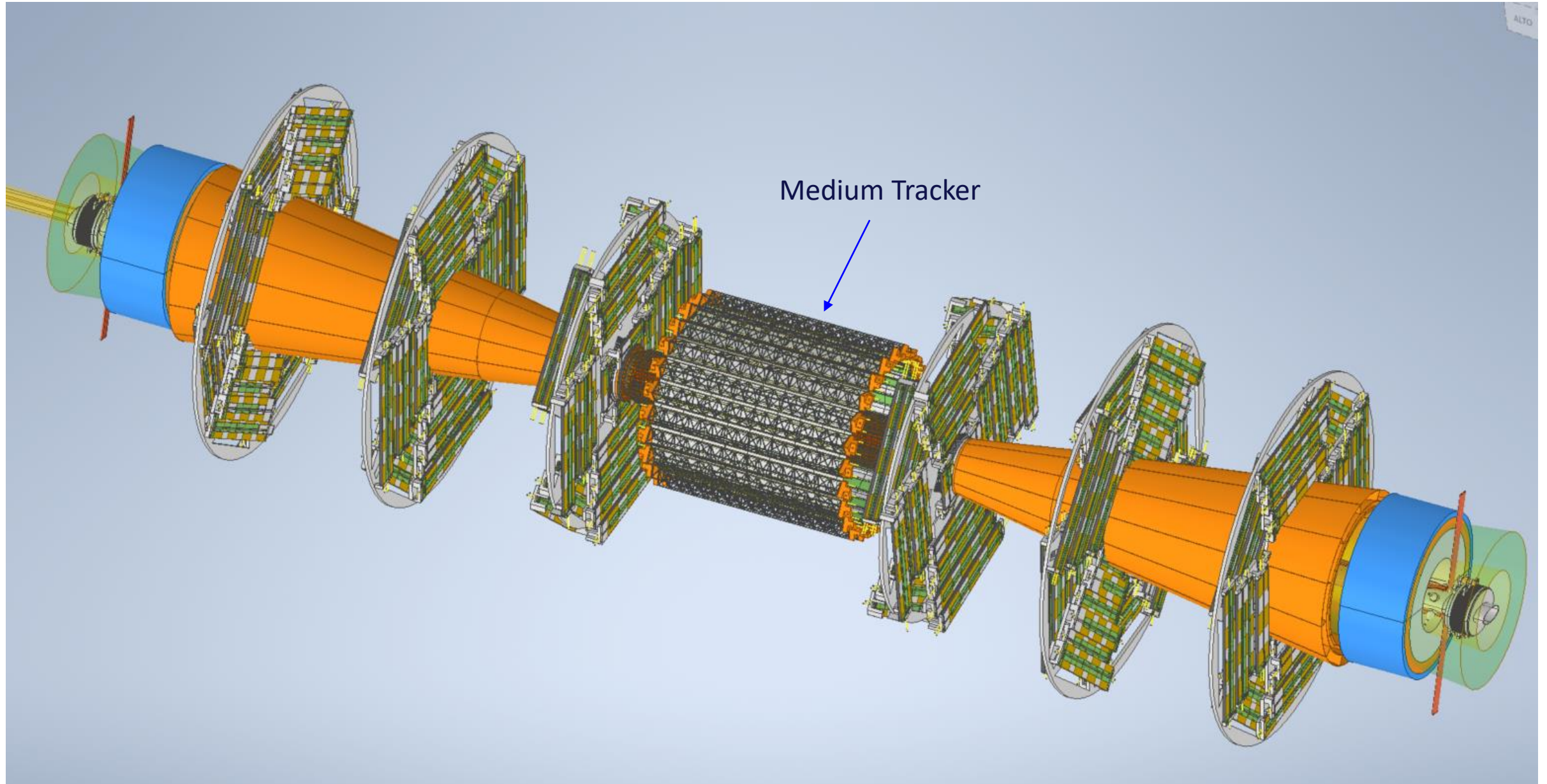


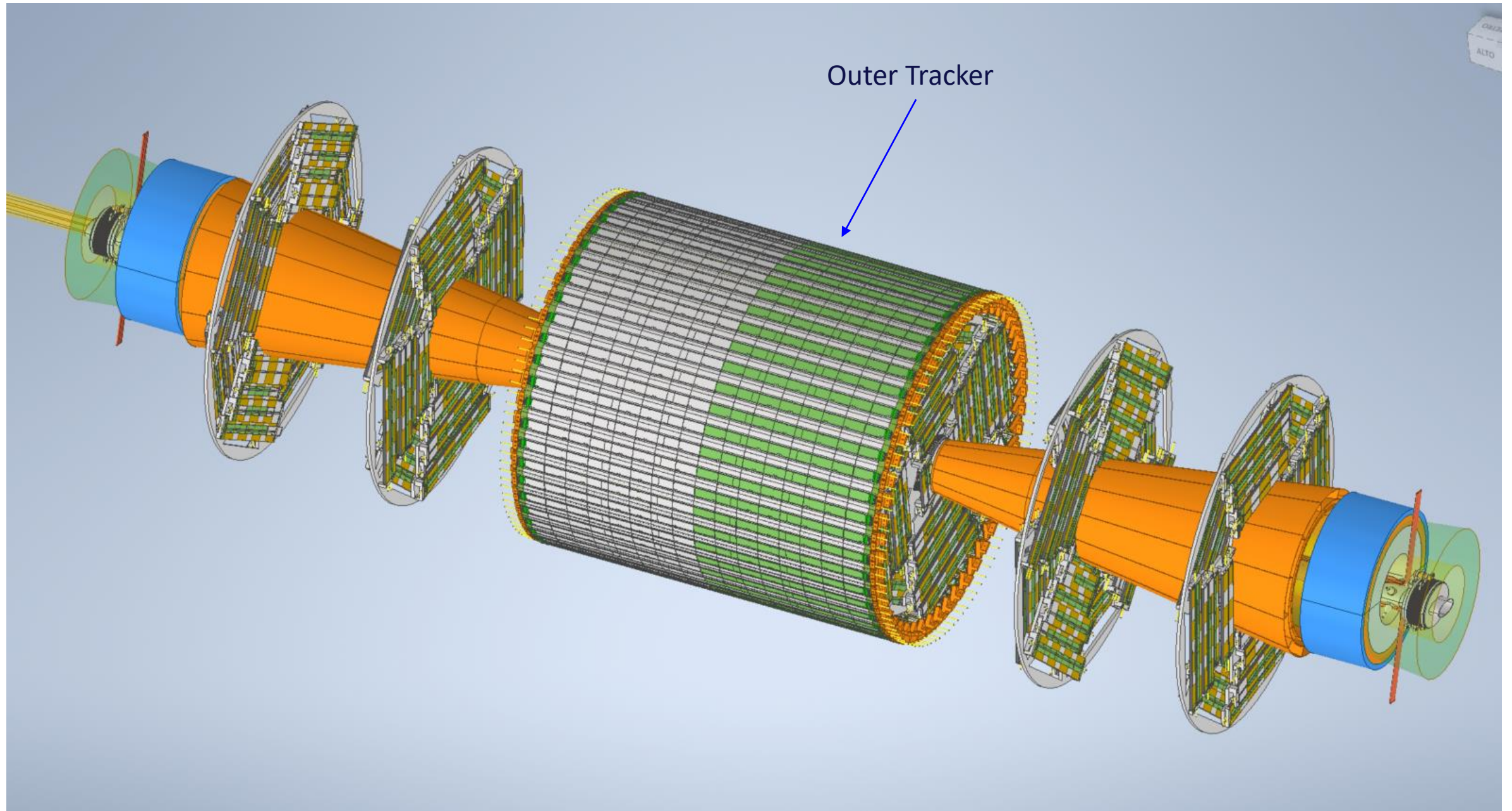
Total power ~120 W
Total weight ~230 grams

Stave detail



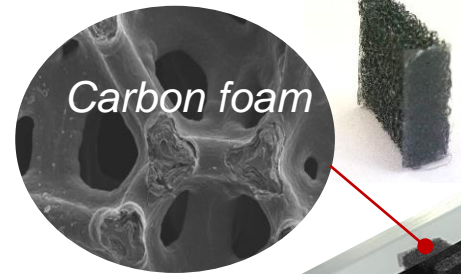
Shaped to minimize material at the end of the stave



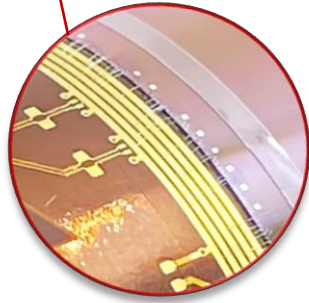


R&D Based on present effort in the design of the ITS3 (RUN4 -LS3)

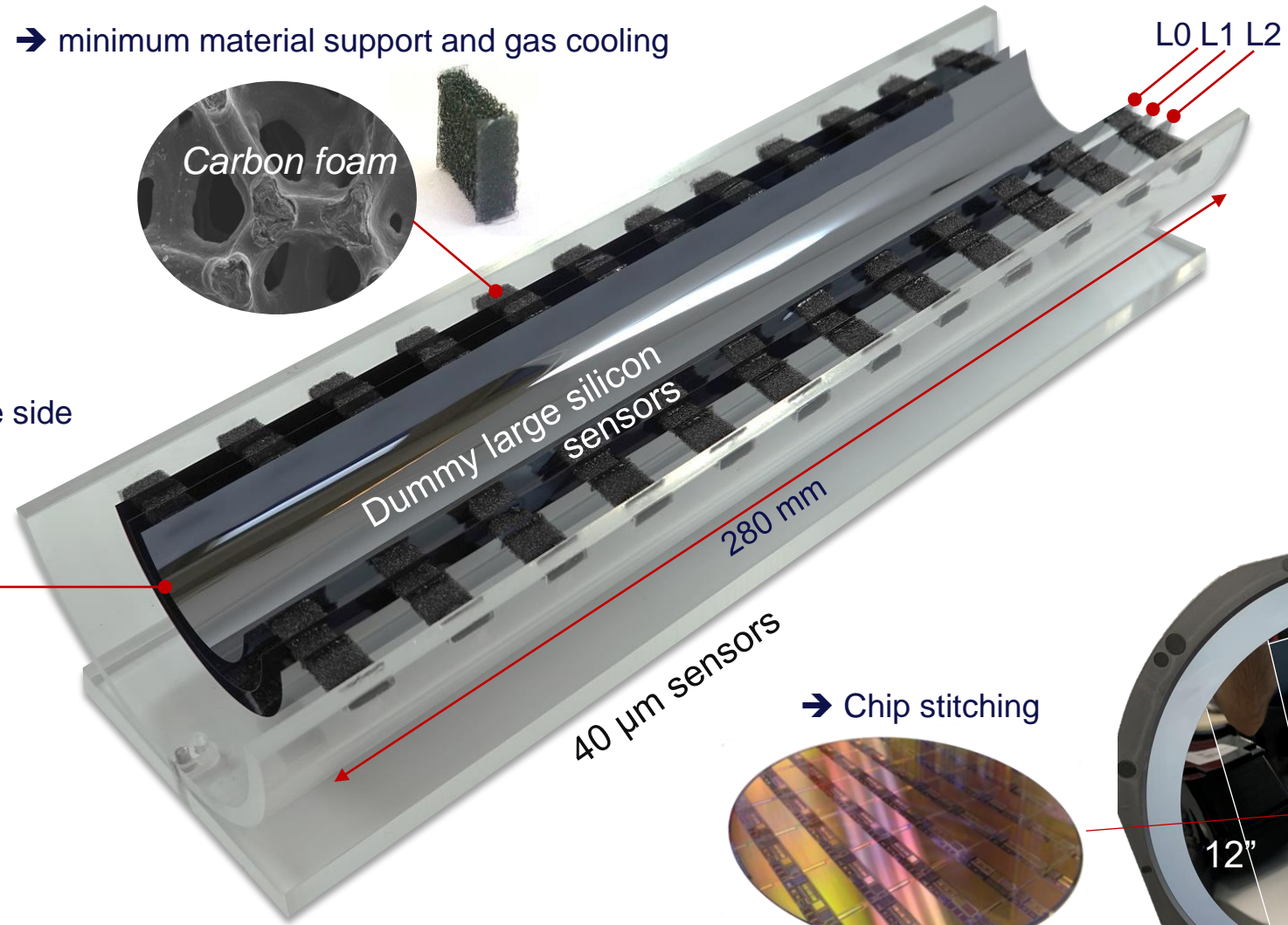
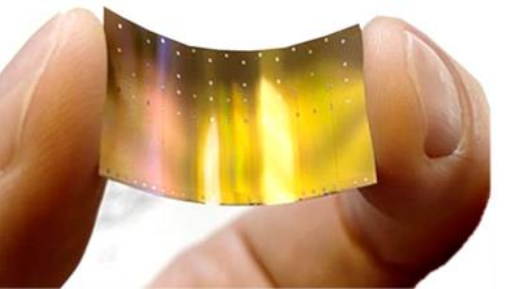
→ minimum material support and gas cooling



→ Wire bonding at the edge side



→ Curved Silicon sensors



→ Chip stitching

